

# System Power Management for Mobile Handset

### **General Description**

The MAX8939/MAX8939A/MAX8939B power management ICs contain the necessary supplies and features for supporting cell phone designs based on the Intel Mobile Communications (IMC) 61XX 3G platform. Designed to power all peripheral components in the platform, the ICs also provide the necessary signals to control the 61XX baseband processor.

The integrated lithium-ion (Li+) charger is protected up to 28V input and features a protected output voltage for supply of a USB transceiver. Proprietary thermal-regulation circuitry limits the die temperature during fast-charging or when the ICs are exposed to high ambient temperatures, allowing maximum charging current without damaging the ICs. A dedicated current regulator is included for driving a charge indicator LED.

Four programmable low-noise, low-dropout linear regulators (LDOs) provide the supply for noise sensitive peripherals. A high power vibrator driver is I<sup>2</sup>C programmable in 70 PWM levels and 4 output voltages. The ICs also offer two step-up converters; one high power, low voltage (5V) to supply an external audio amplifier or camera flash, and a high voltage (28V) supply for the display and keyboard backlight. Two integrated 25mA current regulators provide independent ramp-up and ramp-down control, programmable through I<sup>2</sup>C.

The MAX8939/MAX8939A/MAX8939B are highly integrated ICs that require very few external components and are available in a compact 2.5mm x 3.0mm, 0.65mm max height wafer level package (WLP).

### \_Applications

Companion Chip for Cell Phones/Smartphones

#### **Features**

- ♦ Step-Up Converter
  700mA Guaranteed Output Current
  I²C Programmable Output 3.5V to 5.0V in 16 Steps
  Over 90% Efficiency
  On-Chip FET and Synchronous Rectifier
  Fixed 2MHz PWM Switching
- Small 2.2µH to 10µH Inductor

  ◆ WLED Boost Converter
  28V Max Step-Up Output Voltage
  60mA Output Current
  Integrated nMOS Power Switch
  Over 90% Efficiency
  Fixed 2MHz Switching
  Small 4.7µH to 10µH Inductor
  Two 25mA Individually Programmable Current
  Regulators
  I²C Programmable Output Current (50µA to
  25.25mA) with 128-Step Pseudo Log Dimming
  Individually Programmable Ramp (Up/Down)
  Timers
  Low Dropout (150mV max)

♦ Linear One-Cell Li+ Battery Charger No External MOSFET, Reverse Blocking Diode, or Current-Sense Resistor Programmable Fast-Charge Current (1.5ARMS max for the MAX8939 or 850mARMS max for the MAX8939A/MAX8939B) Programmable Top-Off Current Threshold **Proprietary Die Temperature Regulation Control** 4.1V to 10V Input Voltage Range (MAX8939) 4.1V to 6.25V Input Voltage Range (MAX8939A/ MAX8939B) with Input Overvoltage Protection Up to 28V Low-Dropout Voltage (300mV at 500mA) Input Power-Source Detection Output Input Óvervoltage Protected 4.75V Output (SAFE\_OUT) from IN **Charge Current Monitor Output** Indicator LED

♦ Four Low-Noise LDOs 1x 400mA, 2 x 200mA and 1x 100mA Output Current High 65dB (typ) PSRR Low Noise (45µVRMS typ) 1.7V to 3.2V Programmable Output Voltage Low Quiescent Current (25µA typ) 400mA LDO with Hardware Enable Input

5s Watchdog Feature During Charge

**Hardware Input Enable** 

- ♦ Vibrator Driver Guaranteed 200mA Output Current Programmable Output Voltage 1.3V to V<sub>INVIB</sub> Repetition Frequency 23.8kHz PWM Speed Control in 70 steps Active Stop Brake
- ♦ Control Interface for 61XX Baseband MAX8939/MAX8939A/MAX8939B Control Through I<sup>2</sup>C RESET\_IN Reset Input Charger Detect PWR\_ON\_CMP Output IRQ Interrupt Output
- ♦ 2.9V to 5.5V Supply Voltage Range
- ♦ Thermal Shutdown

### Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX8939EWV+T	-40°C to +85°C	30 WLP (0.5mm pitch)
MAX8939AEWV+T	-40°C to +85°C	30 WLP (0.5mm pitch)
MAX8939BEWV+T	-40°C to +85°C	30 WLP (0.5mm pitch)

+Denotes a lead(Pb)-free/RoHS-compliant package. T = Tape and reel.

Typical Operating Circuit appears at end of data sheet.

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maximintegrated.com.

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#### **ABSOLUTE MAXIMUM RATINGS**

BATT, OUT1, SAFE_OUT, and INVIB to AGND0.3V to +6.0V	/
CHG_IN, OUT2, LED1, and LED2 to AGND0.3V to +30V	/
LED3 and CHG_MON to AGND0.3V to (VSAFE_OUT + 0.3V)	)
COMP2, IRQ, RESET_IN, COMP1, SCL, SDA, CHG,	
PWR_ON_CMP, REF, LDO1, LDO2, LDO3, LDO4,	
and LDO1_EN to AGND0.3V to (VBATT + 0.3V)	)
OUTVIB to AGND0.3V to (VINVIB + 0.3V)	)
PGND1 and PGND2 to AGND0.3V to +0.3V	/

LX1, LX2 Current (Note 1)	1.7ARMS
Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )	
WLP (derate 24.4mW/°C above +70°C)	1.9W
Operating Temperature	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Soldering Temperature (reflow)	+260°C

Note 1: LX1 has internal clamp diodes to PGND1 and OUT1. LX2 has internal clamp diodes to PGND2 and OUT2. Applications that forward bias these diodes should take care not to exceed the IC package power dissipation limit.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **PACKAGE THERMAL CHARACTERISTICS (Note 2)**

WLP

Junction-to-Ambient Thermal Resistance ( $\theta_{JA}$ ) ........41°C/W

**Note 2:** Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to <a href="https://www.maximintegrated.com/thermal-tutorial">www.maximintegrated.com/thermal-tutorial</a>.

### **ELECTRICAL CHARACTERISTICS (Note 3)**

(VBATT = 3.7V, VCHG\_IN = 5.0V, circuit of Figure 1, TA = -40°C to +85°C, unless otherwise noted. Typical values are at TA = +25°C.)

PARAMETER	CONDITIO	DNS	MIN	TYP	MAX	UNITS
BATT						
BATT Operating Voltage			2.9		5.5	V
BATT Shutdown Supply Current	All outputs off, I <sup>2</sup> C disabled,	T <sub>A</sub> = +25°C		0.4	1	
BATT Shuldown Supply Current	VSCL = VSDA= VRESET_IN = 0V	TA = +85°C		0.4	1	- μΑ
DATT Standby Supply Current	All outputs off, V <sub>SCL</sub> = V <sub>SDA</sub> =	$T_A = +25^{\circ}C$		5	10	
BATT Standby Supply Current	VRESET_IN = 1.8V, I <sup>2</sup> C ready	TA = +85°C		5		- μΑ
BATT Biasing Supply Current	I <sup>2</sup> C ready, one or more outputs	on		60		μA
Undervoltage Lockout (UVLO) Threshold	BATT rising		2.6	2.75	2.9	V
Undervoltage Lockout Hysteresis				100		mV
THERMAL SHUTDOWN						
Threshold				+160		°C
Hysteresis				20		°C
REFERENCE						
Reference Output Voltage				1.200		V
Reference Supply Rejection				0.2		mV
LOGIC AND CONTROL INPUTS						
Input Low Level	SDA, SCL, LDO1_EN, CHG, and	RESET_IN			0.4	V
Input High Level	SDA, SCL, LDO1_EN, CHG, and RESET_IN		1.40			V
Ii- I t Comment	SDA, SCL, LDO1_EN, CHG,	T <sub>A</sub> = +25°C	-1		+1	
Logic-Input Current	and RESET_IN, 0 < VIN < 5.5V TA = +85°C			0.1		μΑ

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### **ELECTRICAL CHARACTERISTICS (Note 3) (continued)**

(VBATT = 3.7V, VCHG\_IN = 5.0V, circuit of Figure 1, TA = -40°C to +85°C, unless otherwise noted. Typical values are at TA = +25°C.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
LOGIC AND CONTROL OUTPUTS		'			
IRQ (Open-Drain Output) Output Low Voltage	I <sub>RQ</sub> = 2mA			0.4	V
PWR_ON_CMP (Open-Drain Output) Output Low Voltage	IPWR_ON_CMP = 2mA			0.4	V
SDA Output Low Level	ISDA = 6mA			0.4	V
I <sup>2</sup> C SERIAL INTERFACE (V <sub>SCL</sub> = V	SDA = 3V) (Figure 15)				
Clock Frequency				400	kHz
Bus-Free Time Between START and STOP	tBUF	1.3			μs
Hold Time Repeated START Condition	thD_STA	0.6			μs
SCL Low Period	tLOW	1.3			μs
SCL High Period	thigh	0.6			μs
Setup Time Repeated START Condition	tsu_sta	0.6			μs
SDA Hold Time	thd_dat	0			μs
SDA Setup time	tsu_dat	100			ns
Maximum Pulse Width of Spikes that Must Be Suppressed by the Input Filter of Both DATA and CLK Signals			50		ns
Setup Time for STOP Condition	tsu_sto	0.6			μs
CHG_IN					
Input Operating Range		4.1		10	V
CHG_IN Current	VCHG_IN = 28V, VBATT = 4V, MAX8939A/MAX8939B	400	600	1000	μA
CHG_IN Leakage Current from CHG_IN to BATT	V <sub>CHG_IN</sub> = 28V, V <sub>BATT</sub> = 0V, MAX8939A/MAX8939B		21	80	μΑ
Reverse Leakage Current from BATT to CHG_IN	VCHG_IN = 0V, VBATT = 0 to 4.2V, MAX8939A/ MAX8939B			10	μΑ
	VCHG_IN - VBATT, rising	200	300	400	
CHG_IN Trip Point	VCHG_IN - VBATT, falling		100		mV
	V <sub>CHG_IN</sub> - V <sub>BATT</sub> , hysteresis		200		
	MAX8939, VCHG_IN rising, 500mV hysteresis (typ)	3.9	4.0	4.1	
Input Undervoltage Threshold (UV)	MAX8939A/MAX8939B, VCHG_IN rising, 900mV hysteresis (typ)	3.9	4.0	4.1	V
	MAX8939, V <sub>CHG_IN</sub> rising, 200mV hysteresis (typ)	10.2	10.6	11	
Input Overvoltage Threshold (OVP)	MAX8939A/MAX8939B, V <sub>CHG_IN</sub> rising, 200mV hysteresis (typ)	6.25	6.5	6.75	V
Input Supply Current	ICHG_IN - IBATT = 90mA		750	1500	μA
Shutdown Input Current	Charger disabled			500	μΑ

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### **ELECTRICAL CHARACTERISTICS (Note 3) (continued)**

 $(V_{BATT} = 3.7V, V_{CHG\_IN} = 5.0V, circuit of Figure 1, T_A = -40^{\circ}C to +85^{\circ}C, unless otherwise noted. Typical values are at T_A = +25^{\circ}C.)$ 

PARAMETER	COND	MIN	TYP	MAX	UNITS	
CHG_IN to BATT Dropout On-Resistance	V <sub>C</sub> HG_IN = 3.7V, V <sub>B</sub> ATT = 3.6V			0.4	0.8	Ω
SAFE_OUT			•			
	ISAFE_OUT = 15mA, V <sub>CHG_IN</sub> T <sub>A</sub> = 0°C to +85°C	1 = 5V,	4.75	4.90	5.00	
SAFE_OUT Regulated Output	ISAFE_OUT = 15mA, V <sub>CHG_IN</sub> T <sub>A</sub> = 0°C to +85°C	ι = 10V,			5.2	V
SAFE_OUT Current Limit			100		mA	
CHG_MON	•					
I/V Conversion Factor	Monitoring voltage to charge current = 450mA (Note 4)	current - fast-charge		2.666		mV/ mA
I/V Accuracy	Overall range		-10		+10	%
Output Voltage	450mA charge current - fast- (Note 4)	-charge current = 450mA		1200		mV
Charge Monitoring Range			0		1.2	V
Output Impedance		10	20	40	kΩ	
INDICATOR LED	•			,		
LED3 Current Sink	V <sub>C</sub> HG <sub>IN</sub> = 5V, T <sub>A</sub> = 0°C to +	-85°C	1.5	3	5	mA
BATT	•		•			
BATT Regulation Voltage	IBATT = 90mA,	T <sub>A</sub> = +25°C	4.179	4.2	4.221	V
(MAX8939)	VBATT programmed to 4.2V	$T_A = -40$ °C to $+85$ °C	4.158	4.2	4.242	]
	I <sub>BATT</sub> = 90mA, T <sub>A</sub> = +25°C	VSET = 11b	4.129	4.150	4.171	
DATT Degulation Valtage		VSET = 00b	3.465	3.500	3.535	]
BATT Regulation Voltage (MAX8939A)	IBATT = 90mA,	VSET = 01b	3.811	3.850	3.889	V
(W/ VCCCC) ()	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	VSET = 10b	4.009	4.050	4.091	
		VSET = 11b	4.108	4.150	4.192	
	$I_{BATT} = 90 \text{mA}, T_A = +25 ^{\circ}\text{C}$	VSET = 11b	4.149	4.170	4.191	
		VSET = 00b	3.465	3.500	3.535	] ,,
BATT Regulation Voltage	IBATT = 90mA,	VSET = 01b	3.811	3.850	3.889	\ \
(MAX8939B)	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	VSET = 10b	4.009	4.050	4.091	1
		VSET = 11b	4.129	4.170	4.192	
Programmable Restart Fast-Charge Threshold	From BATT regulation voltage, default = disable  -200 -300 -400 Disable					mV

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### **ELECTRICAL CHARACTERISTICS (Note 3) (continued)**

(VBATT = 3.7V, VCHG\_IN = 5.0V, circuit of Figure 1, TA = -40°C to +85°C, unless otherwise noted. Typical values are at TA = +25°C.)

PARAMETER			COND	IOITI	NS	MIN	TYP	MAX	UNITS	
		CHO	G_CONTRO	OL_A	.FAST_CHARGE = 000b	80	90	100		
		001b				240	270	300	1	
		010	b			400	450	500	1	
CHG_IN Fast-Charge Current	V <sub>BATT</sub> = 3.5V	011	b			560	630	700	mA	
(MAX8939) (Note 5)	VBATT = 3.5V	100	b			630	765	900		
		101	b			700	850	1000		
		110	b			940	1020	1200		
		111	b			1050	1275	1500		
		CHC	G_CONTRO	OL_A	.FAST_CHARGE = 000b	82	90	98		
		001	b			250	270	290		
		010	b			420	450	480		
CHG_IN Fast-Charge Current	VBATT = 3.5V	011	b			575	630	685	mA	
(MAX8939A/MAX8939B) (Note 5)	VBATT = 0.5V	100	b			695	765	835		
		101	b			775	850	925	]	
		110b			100	120	140			
		111b			160	180	200			
CHG_IN Precharge Current	V <sub>BATT</sub> = 2V						90	100	mA	
BATT Prequalification Threshold Voltage	VBATT rising hysteresis 140mV (		าV (ty	/p)	2.5	2.55	2.6	V		
Soft-Start Time	Ramp time to	fast-c	charge cu	rrent			2.5		ms	
TOP-OFF										
		TOP_OFF = 00b		_OFF = 00b		10				
Top-Off Threshold	6.115			TOP	_OFF = 01b		20		7 .	
(% of Fast-Charge Current)	IBATT falling			TOP	_OFF = 10b		30		%	
				TOP	_OFF = 11b (default)	0			1	
TIMER										
Timer Accuracy						-20		+20	%	
					CCTR = 00b (default)		60			
			MAX893	9	CCTR = 01b		120			
5 . O	From entering				CCTR = 10b		240		1 .	
Fast-Charge Time Limit	charge to V <sub>BA</sub>	TT			CCTR = 00b (default)		24		- min	
	7.2 V		MAX893		CCTR = 01b		120		┥ !	
			MAX8939B		CCTR = 10b		240			
D. J. T.	MAX8939					30				
Precharge Timer	MAX8939A/M	4X89	39B				12		min	

# System Power Management for Mobile Handset

## **ELECTRICAL CHARACTERISTICS (Note 3) (continued)**

 $(V_{BATT} = 3.7V, V_{CHG\_IN} = 5.0V, circuit of Figure 1, T_{A} = -40^{\circ}C to +85^{\circ}C, unless otherwise noted. Typical values are at T_{A} = +25^{\circ}C.)$ 

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS	
	TOPOFF_TIME = 00b		30				
	TOPOFF_TIME = 01b		60		1 .		
Top-Off Timer	TOPOFF_TIME = 10b		120		min		
	TOPOFF_TIME = 11b			Disable			
	MAX8939		2.5	5	10		
Watchdog Timer		MAX8939A/MAX8939B		30	45	s	
THERMAL LOOP	WIT VIOLOGIA (IVIII VIOLOGIA		15		-10		
		+70°C [00]					
	Junction temperature when the charge current is	+85°C [01]					
Thermal Limit Temperature	reduced, T <sub>J</sub> rising, default	+100°C [10]		+100		°C	
	value						
OUT4 OTER UR DO DO CONVE	TED.	+115°C [11]					
OUT1 STEP-UP DC-DC CONVER	11EK		0.0			l v	
Input Voltage (VBATT)	01411 1111 1111 1111		2.9		5.5	1	
Input Supply Current	2MHz switching, V <sub>OUT</sub> = 5V	1	0	11	. 0	mA	
OUT1 Voltage Accuracy	500mA load	T <sub>A</sub> = +25°C	-3		+3	%	
		T <sub>A</sub> = +85°C	-4	700	+4		
Maximum Output Current	V <sub>BATT</sub> ≥ 3.2V, V <sub>OUT1</sub> = 5.0V		550	700		mA .	
nFET Current Limit			2.0			A	
Line Regulation	V <sub>BATT</sub> = 2.9V to 4.2V			0.1		%/V	
Load Regulation	0 to 500mA load		0.5		%/A		
LX1 nFET On-Resistance	LX1 to PGND1, $I_{LX1} = 200$ m			0.1	0.2	Ω	
LX1 pFET On-Resistance	LX1 to OUT1, $I_{LX1} = -200 \text{m/s}$	T		0.15	0.3	Ω	
LX1 Leakage	$V_{LX1} = 5.5V$	T <sub>A</sub> = +25°C		0.01	5	μΑ	
_	1221	T <sub>A</sub> = +85°C		0.1			
Switching Frequency			1.8	2	2.2	MHz	
Maximum Duty Cycle			65	75		%	
Minimum Duty Cycle				8		%	
COMP Discharge Resistance	During shutdown or UVLO			220		Ω	
VIBRATOR						1	
Programmable Output Voltage OUTVIB	1mA at VBATT = VINVIB = 5. VINVIB = 3.4V, default value			3		V	
Output Current				,	200	mA	
Current Limit	VOUTVIB = 0V	VOUTVIB = 0V			600	mA	
Dropout Voltage	$I_{LOAD} = 135 \text{mA}, T_A = +25 ^{\circ} C$		150	300	mV		
Line Regulation	3.4V ≤ V <sub>BATT</sub> = V <sub>INVIB</sub> < 5.5V, I <sub>LOAD</sub> = 100mA			2.2		mV	
Load Regulation	1mA < I <sub>LOAD</sub> < 200mA			25		mV	
Power-Supply Rejection ΔVINVIB/ΔVOUTVIB	f = 10Hz to 10kHz, I <sub>LOAD</sub> =		40		dB		
Output Noise	100Hz to 100kHz, ILOAD = 3	 30mA		65		μVRMS	
Discharge Time Constant	Toff 90% to 5%, $C = 1\mu F$			0.1		ms	

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### **ELECTRICAL CHARACTERISTICS (Note 3) (continued)**

(VBATT = 3.7V, VCHG IN = 5.0V, circuit of Figure 1, TA = -40°C to +85°C, unless otherwise noted. Typical values are at TA = +25°C.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Active Stop	nFET on-resistance		1		Ω
Active Brake on Shutdown	nFET on duration		85		ms
LDO1					
Output Accuracy	I <sub>LOAD</sub> = 1mA	-3		+3	%
Maximum Output Current		400			mA
Current Limit	$V_{LDO1} = 0V$		600		mA
Dropout Voltage	ILOAD = 200mA		200	400	mV
Line Regulation	3.4V ≤ V <sub>BATT</sub> ≤ 5.5V, I <sub>LOAD</sub> = 100mA		2.4		mV
Load Regulation	50μA < I <sub>LOAD</sub> < 200mA		25		mV
Power-Supply Rejection ΔVLDO1/ΔVBATT	f = 10Hz to 10kHz, ILOAD = 30mA		60		dB
Output Noise Voltage (RMS)	100Hz to 100kHz, I <sub>LOAD</sub> = 30mA		50		μVRMS
Ground Current	I <sub>LOAD</sub> = 500μA		21		μΑ
Shutdown Discharge Time	Toff 90% to 10%, $C = 4.7\mu F$			1	ms
Shutdown Output Impedance			50	80	Ω
LDO2, LDO3					
Output Accuracy	I <sub>LOAD</sub> = 1mA	-3		+3	%
Maximum Output Current		200			mA
Current Limit	Output = 0V		400	700	mA
Dropout Voltage	ILOAD = 135mA		200	400	mV
Line Regulation	3.4V ≤ V <sub>BATT</sub> ≤ 5.5V, I <sub>LOAD</sub> = 100mA		2.4		mV
Load Regulation	50μA < ILOAD < 200mA		25		mV
Power-Supply Rejection ΔVLDO_/ΔVBATT	f = 10Hz to 10kHz, I <sub>LOAD</sub> = 30mA		60		dB
Output Noise Voltage (RMS)	100Hz to 100kHz, I <sub>LOAD</sub> = 30mA		50		μVRMS
Ground Current	$I_{LOAD} = 500\mu A$		21		μΑ
Shutdown Discharge Time	$T_{OFF}$ 90% to 10%, $C = 1\mu F$			1	ms
Shutdown Output Impedance	·		100	150	Ω
LDO4		'			
Output Accuracy	ILOAD = 1mA	-3		+3	%
Maximum Output Current		100			mA
Current Limit	$V_{LDO4} = 0V$		200	400	mA
Dropout Voltage	I <sub>LOAD</sub> = 70mA		200	400	mV
Line Regulation	3.4V ≤ V <sub>BATT</sub> ≤ 5.5V, I <sub>LOAD</sub> = 50mA		2.4		mV
Load Regulation	50μA < ILOAD < 100mA		25		mV
Power-Supply Rejection ΔVLDO4/ΔVBATT	$f = 10Hz$ to $10kHz$ , $I_{LOAD} = 30mA$		60		dB
Output Noise	100Hz to 100kHz, I <sub>LOAD</sub> = 30mA		50		μVRMS
Ground Current	ILOAD = 500µA		25		μΑ
Shutdown Discharge Time	Toff 90% to 10%, C = 1µF			1	ms
Shutdown Output Impedance	·		100	150	Ω

# System Power Management for Mobile Handset

### **ELECTRICAL CHARACTERISTICS (Note 3) (continued)**

(VBATT = 3.7V, VCHG\_IN = 5.0V, circuit of Figure 1, TA = -40°C to +85°C, unless otherwise noted. Typical values are at TA = +25°C.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
<b>OUT2 WLED STEP-UP CONVERTE</b>	R				
Input Supply Voltage		2.9	,	5.5	V
Input Supply Current	2MHz, no load		2	2.5	mA
OLITA Lankaga Current	$T_A = +25$ °C, $V_{OUT2} = 5.5V$ , shutdown		0.01	1	
OUT2 Leakage Current	$T_A = +85$ °C, $V_{OUT2} = 5.5V$ , shutdown		0.1	5	μΑ
LED1, LED2		•			
Current Regulator Dropout Voltage (Note 6)	25.25mA setting			200	mV
LED_ Regulation Voltage			350		mV
LED Comment Assumes	T <sub>A</sub> = +25°C, I <sub>LED</sub> = 25.25mA	-3		+3	0/
LED_ Current Accuracy	$T_A = -40^{\circ}C$ to +85°C, ILED_= 25.25mA	-5		+5	%
Landana Commant	$T_A = +25$ °C, in shutdown		0.01	1	
Leakage Current	$T_A = +85$ °C, in shutdown		0.1	5	μA
LX2					•
nFET Current Limit		710	860		mA
nFET On-Resistance	$I_{LX2} = 200 \text{mA}$		0.3	0.7	Ω
LV2 Lookaga Current	$T_A = +25$ °C, 5.5V, shutdown		0.01	1	
LX2 Leakage Current	$T_A = +85$ °C, 5.5V, shutdown		0.1	5	μA
Operating Frequency		1.8	2	2.2	MHz
Maximum Duty Cycle	V <sub>LED1</sub> or V <sub>LED2</sub> = 0.2V		90		%
COMP2		·			
Transconductance			20		μs
Soft-Start Charge Current			60		μΑ
Discharge Pulldown			20		kΩ
PROTECTION					
Overvoltage Threshold	V <sub>OUT2</sub> rising	28		30	V
Overvoltage Hysteresis			4		V
Open LED Detection			100	120	mV
Shorted LED Detection		VOUT2 - 2.2V	V <sub>OUT2</sub> - 0.7V		V

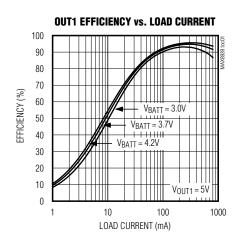
- **Note 3:** Limits are 100% production tested at TA = +25°C, unless otherwise noted. Min/max limits over the operating temperatures range and relevant supply voltage range are guaranteed by design and characterization. Typical values are not guaranteed.
- **Note 4:** The monitoring voltage is proportional to the charging current with a ratio depending on the programmed fast-charge current. For the current equal to the fast-charge current, the monitoring voltage is typically 1.2V.
- Note 5: The maximum CHG\_IN current is the typical value plus 10% for currents up 700mA and the typical value plus 15% for higher currents.
- **Note 6:** LED dropout voltage is defined as the LED\_ to ground voltage when current into LED\_ drops 10% from the value at VLED\_= 0.5V.

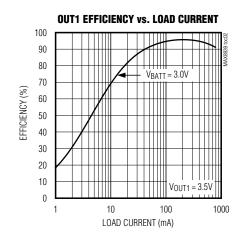
# System Power Management for Mobile Handset

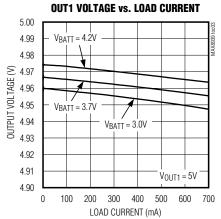
### Typical Operating Characteristics

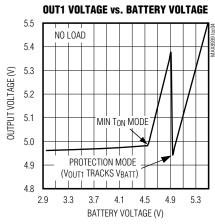
(VBATT = 3.7V, circuit of Figure 1, TA = +25°C, unless otherwise noted.)

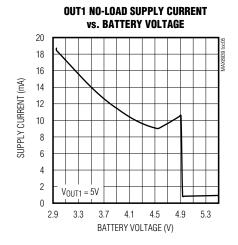
#### **OUT1 STEP-UP CONVERTER**

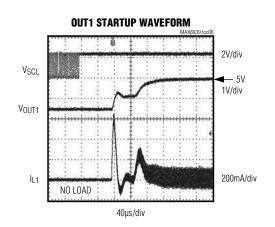










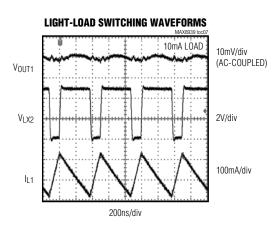


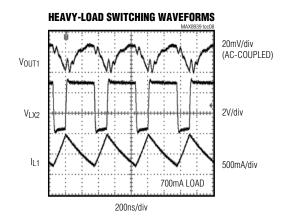
# System Power Management for Mobile Handset

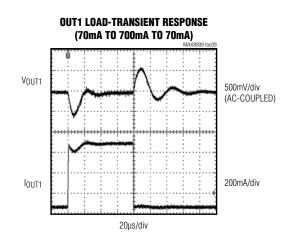
## Typical Operating Characteristics (continued)

(VBATT = 3.7V, circuit of Figure 1, TA = +25°C, unless otherwise noted.)

### **OUT1 STEP-UP CONVERTER (CONTINUED)**







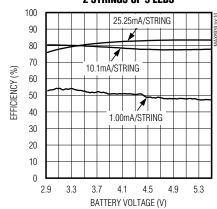
# System Power Management for Mobile Handset

### **Typical Operating Characteristics (continued)**

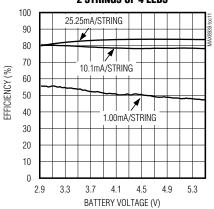
(VBATT = 3.7V, circuit of Figure 1, TA = +25°C, unless otherwise noted.)

#### **OUT2 WHITE LED DRIVER**

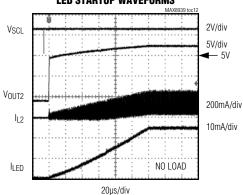
# LED EFFICIENCY vs. BATTERY VOLTAGE 2 STRINGS OF 5 LEDS



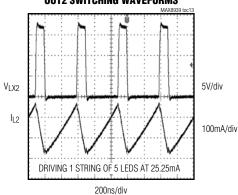
#### LED EFFICIENCY vs. BATTERY VOLTAGE 2 STRINGS OF 4 LEDS



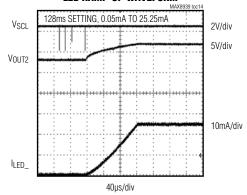
#### **LED STARTUP WAVEFORMS**



#### **OUT2 SWITCHING WAVEFORMS**



#### **LED RAMP-UP WAVEFORM**

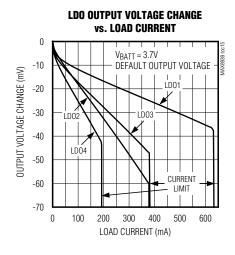


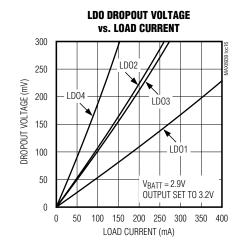
# System Power Management for Mobile Handset

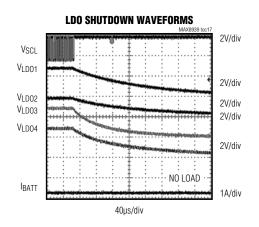
## **Typical Operating Characteristics (continued)**

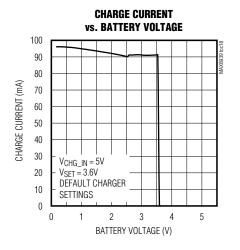
(VBATT = 3.7V, circuit of Figure 1, TA = +25°C, unless otherwise noted.)

#### **LDOs**







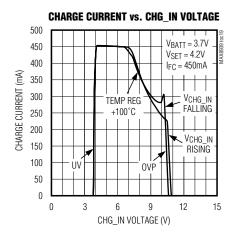


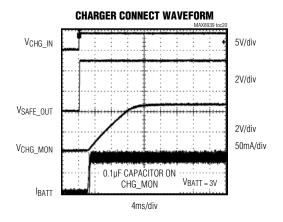
# System Power Management for Mobile Handset

### **Typical Operating Characteristics (continued)**

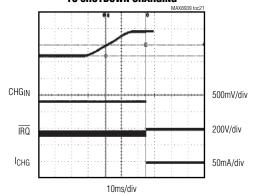
(VBATT = 3.7V, circuit of Figure 1, TA = +25°C, unless otherwise noted.)

#### **BATTERY CHARGER**

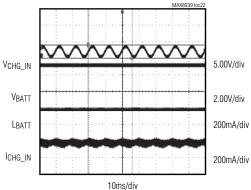




#### DEBOUNCE TIME FROM OVP DETECT TO SHUTDOWN CHARGING

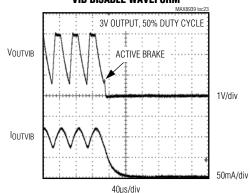


# CHARGER CONTINUES CHARGING AT HIGH INPUT RIPPLE > 7Hz AND DC LEVEL < OVP THRESHOLD



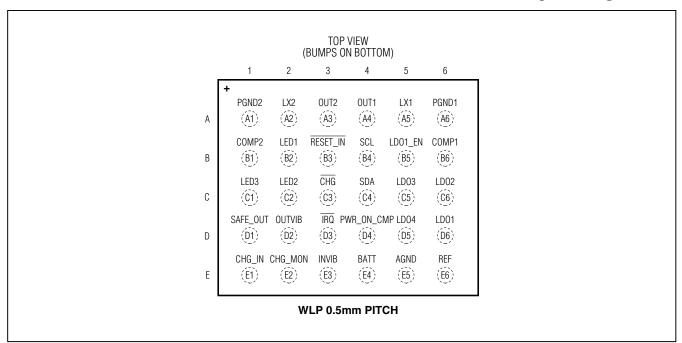
#### **VIBRATOR DRIVER**

#### **VIB DISABLE WAVEFORM**



# System Power Management for Mobile Handset

### **Bump Configuration**



### **Bump Description**

PIN	NAME	FUNCTION
A1	PGND2	Power Ground for WLED Boost Converter. Connect PGND1, PGND2, and AGND to the PCB ground plane.
A2	LX2	Inductor Connection and Switching Node for WLED Boost Converter
А3	OUT2	WLED Step-Up Converter Output. Connect a 1µF capacitor from OUT2 to PGND2.
A4	OUT1	Step-Up Converter Output. Connect a 2.2µF capacitor from OUT1 to ground.
A5	LX1	Inductor Connection and Switching Node for OUT1 Step-Up Converter
A6	PGND1	Power Ground for OUT1 Step-Up Converter. Connect PGND1, PGND2, and AGND to the PCB ground plane.
B1	COMP2	Step-Up Compensation Node for OUT2 Step-Up Converter. Connect a $0.22\mu F$ ceramic capacitor from COMP to ground. The applied COMP capacitance stabilizes the converter and sets the soft-start time. COMP discharges to ground through a $20k\Omega$ resistance when in shutdown.
B2	LED1	25mA LED Current Regulator. Connect LED1 to the cathode of the first LED string.
В3	RESET_IN	Active-Low Reset Input. Pulse RESET_IN low to reset all registers (except STATUS and EVENT) to their default state.
B4	SCL	Clock Input for I <sup>2</sup> C Serial Interface. High impedance when the I <sup>2</sup> C interface is off.
B5	LDO1_EN	Enable Input for LDO1. Drive LDO1_EN high to enable LDO1, or low to disable LDO1. Once LDO1 is enabled or disabled through I <sup>2</sup> C, the state of LDO1_EN is ignored until reset.
В6	COMP1	Compensation for OUT1 Step-Up Converter. Connect a 2200pF capacitor from COMP1 to ground. See the <i>Soft-Start OUT1</i> section for more details.

# System Power Management for Mobile Handset

### **Bump Description (continued)**

PIN	NAME	FUNCTION
C1	LED3	Indicator LED Connection. Connect LED3 to the cathode of the precharge indicator LED. If a precharge indicator LED is not used, leave LED3 unconnected.
C2	LED2	25mA LED Current Regulator. Connect LED2 to the cathode of the second LED string.
C3	CHG	Charger Disable Input. Connect $\overline{\text{CHG}}$ high to disable the charger, or low to enable the charger. Once the charger is enabled or disabled through I <sup>2</sup> C, the state of $\overline{\text{CHG}}$ is ignored until reset.
C4	SDA	Data Input for Serial Interface. High impedance when the I <sup>2</sup> C interface is off.
C5	LDO3	200mA LDO Output. Connect a 2.2 $\mu$ F capacitor from LDO3 to ground. In shutdown, LDO3 is pulled to ground through an internal 100 $\Omega$ .
C6	LDO2	200mA LDO Output. Connect a 2.2 $\mu$ F capacitor from LDO2 to ground. In shutdown, LDO2 is pulled to ground through an internal 100 $\Omega$ .
D1	SAFE_OUT	4.9V Regulated LDO Output with Input Overvoltage Protection. Connect a 1µF ceramic capacitor from SAFE_OUT to ground. SAFE_OUT can be used to supply low-voltage-rated USB systems and the precharge indicator.
D2	OUTVIB	Vibrator Driver Output. Connect OUTVIB to the vibrator motor. Connect a 1µF ceramic capacitor from OUTVIB to ground.
D3	ĪRQ	Interrupt Request Open-Drain Output
D4	PWR_ON _CMP	Open-Drain Output to Wake Sleeping Baseband. PWR_ON_CMP pulses low while the charger is connected. See the <i>PWR_ON_CMP</i> section for details.
D5	LDO4	100mA LDO Output. Connect a $1\mu F$ capacitor from LDO4 to ground. In shutdown, LDO4 is pulled to ground through an internal $100\Omega$ .
D6	LDO1	400mA LDO Output. Connect a 4.7 $\mu$ F capacitor from LDO1 to ground. In shutdown, LDO1 is pulled to ground through an internal 50 $\Omega$ .
E1	CHG_IN	Charger Input Supply Voltage. CHG_IN is the power-supply input for the SAFE_OUT linear regulator and the battery charger. The operating range for the charger input is 4.1V to 10V (MAX8939) or 6.25V (MAX8939A/MAX8939B). CHG_IN is protected up to 28V. When VCHG_IN exceeds 10.6V (MAX8939) or 6.75 (MAX8939A/MAX8939B), SAFE_OUT and the charger are disabled. Connect a 1µF or larger ceramic capacitor from CHG_IN to ground.
E2	CHG_MON	Charge Current Monitoring Analog Output. CHG_MON outputs a voltage proportional to the charge current with 1.2V corresponding to the programmed fast-charge current. The CHG_MON output includes ripple from loads on the battery. If this is not desired, connect a small 0.01µF to 0.1µF capacitor at the input of the ADC to filter the ripple.
E3	INVIB	Input Supply for the Vibrator Driver. Connect INVIB to BATT. Connect a 1µF ceramic capacitor from INVIB to PGND.
E4	BATT	Battery Connection and IC Supply Voltage. Connect a 10µF ceramic capacitor from BATT to ground.
E5	AGND	Analog Ground. Connect PGND1, PGND2, and AGND to the PCB ground plane.
E6	REF	Reference Noise Bypass. Connect a 0.1µF ceramic capacitor from REF to AGND. Do not load. REF is high impedance when shut down.

# System Power Management for Mobile Handset

**Table 1. Output Summary** 

SUPPLY	OUTPUT RANGE	DEFAULT STATE AT POWER-UP	DEFAULT VALUE (V)	VOLTAGE TOLERANCE (%)	OUTPUT CURRENT (mA)	DESCRIPTION
LDO1	1.7V to 3.2V in 100mV step	Off	2.9	±3.0	400	Low-noise LDO to supply power either to the RF or analog section. LDO1 is controlled from the I <sup>2</sup> C bus or the LDO1_EN input.
LDO2	1.7V to 3.2V in 100mV step	Off	1.8	±3.0	200	Low-noise LDO to supply power either to the RF or analog section. LDO2 is controlled from the I <sup>2</sup> C bus.
LDO3	1.7V to 3.2V in 100mV step	Off	2.8	±3.0	200	Low-noise LDO to supply power either to the RF or analog section. LDO3 is controlled from the I <sup>2</sup> C bus.
LDO4	1.7V to 3.2V in 100mV step	Off	2.8	±3.0	100	Low-noise LDO to supply power either to the RF or analog section. LDO4 is controlled from the I <sup>2</sup> C bus.
OUT1 (STEP-UP)	3.5V to 5.0V in 100mV step	Off	5	±3.0	700	The OUT1 step-up converter provides a 5V power supply for an audio amplifier. The output voltage is programmable through I <sup>2</sup> C.
OUT2 (LED)	V <sub>BATT</sub> to 28V	Off	N/A	N/A	60	The OUT2 step-up converter operates at 2MHz and provides a high-voltage source for the keypad and backlight display drivers.
OUTVIB (Vibrator)	1.3V, 2.5V, 3V, or INVIB bypass	Off	3	±3.0	200	High-power vibrator driver with programmable output voltage and speed control in 70 steps through I <sup>2</sup> C. The vibrator driver has active brake with stop.
Battery Charger	One-cell Li+ MAX8939: 3.6V, 4.15V, 4.20V, or 4.25V MAX8939A/ MAX8939B: 3.50V, 3.85V, 4.05V, or 4.17V	N/A*	MAX8939: 3.6 MAX8939A/ MAX8939B: 3.5	±0.6	90 default MAX8939: 1.3A (max) MAX8939A/ MAX8939B: 850mA (max)	A stand-alone constant-current, constant voltage (CC/CV), thermally regulated linear charger designed for charging a single-cell lithium-ion (Li+) battery. The charger current and protection timer is programmable through I <sup>2</sup> C.
SAFE_OUT	4.9V	N/A*	4.9	±3.0	100 (max)	Protected output SAFE_OUT can be used to supply low-voltage-rated USB systems and the precharge indicator. The output voltage is a fixed 4.9V.

<sup>\*</sup>Subject to valid voltage present at CHG\_IN.

# System Power Management for Mobile Handset

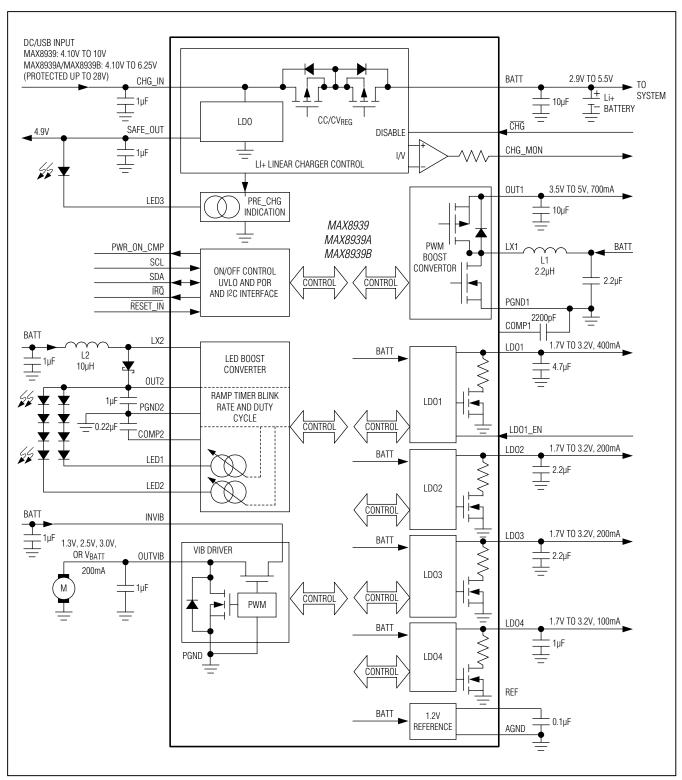


Figure 1. Typical Application Circuit and Block Diagram

# System Power Management for Mobile Handset

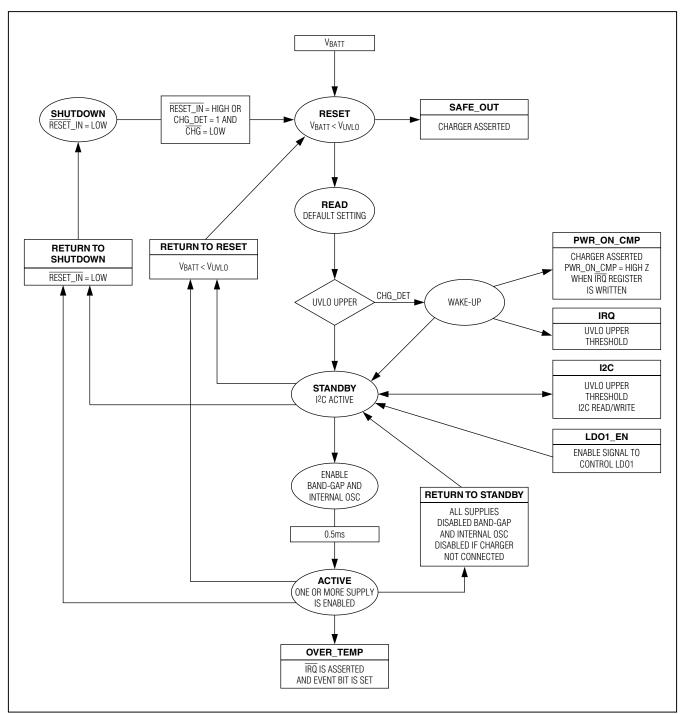


Figure 2. MAX8939/MAX8939A/MAX8939B State Diagram

# System Power Management for Mobile Handset

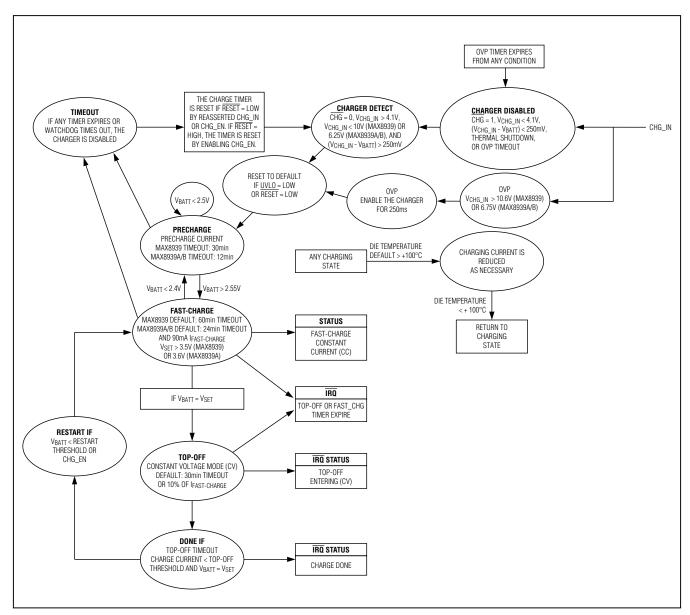


Figure 3. Battery Charger State Diagram

# System Power Management for Mobile Handset

### **Detailed Description**

#### Startup and Power States

To guarantee the correct startup of the MAX8939/MAX8939A/MAX8939B, an internal power-on reset is generated after the first connection of the battery. This resets the I<sup>2</sup>C registers to the default values. The ICs are then in reset state. The reset state is a low power level, where the I<sup>2</sup>C interface is disabled and it is not possible to read or write to any register. The ICs stay in reset state as long as VBATT is below the UVLO upper threshold. When the battery voltage exceeds the UVLO upper threshold, the ICs enter the standby state and the I<sup>2</sup>C bus can be written to. The typical response time of the UVLO detection is 50µs.

The UVLO upper threshold can be reached three ways:

- Fully charge battery is inserted and RESET is logic-high.
- RESET changes from logic-low to logic-high and VBATT > VUVLO UPPER.
- Charger is detected and CHG is logic-low.

#### Standby

Standby is a low-power state where the I<sup>2</sup>C is ready for read/write operations and enables the different power units (Table 1). If a unit is enabled through I<sup>2</sup>C or CHG\_IN is powered, the bandgap and internal oscillator are started and the ICs move to the active state. The ICs stay in the active state until the last unit (including the charger) is disabled.

#### Reset

The ICs enter the reset state when the battery voltage drops below the UVLO lower threshold. In reset, all registers are reset except the STATUS and EVENT registers that retain their values as long as the battery is connected. In reset, all power units are disabled and only the UVLO and CHG\_IN detection circuitry is active. If a fully charged battery is inserted or a charger is detected, the ICs enter standby. If a valid charger is connected, the state machine enables the PWR\_ON\_CMP generator and an interrupt is sent to the host when above the UVLO upper threshold. When a valid charger is detected while in the reset state, the SAFE\_OUT LDO is enabled and the charger begins precharging the battery.

#### Shutdown

The shutdown state is an extremely low-power state. To enter shutdown, hold  $\overline{\text{RESET}}$  logic-low.

In shutdown, all the internal blocks are disabled except the CHG\_IN detection. If CHG\_IN is asserted, the ICs move to the reset state and starts charging with the default settings. When entering from shutdown, the charger is reset and the PWR\_ON\_CMP generator is enabled. If the charger is removed, the ICs move back to the shudown state if RESET is still logic-low.

#### Charger

The ICs' charger uses voltage, current, and thermal-control loops to charge a single Li+ cell and to protect the battery. A complete charge cycle covers four states: prequalification (precharge), constant current fast-charge (CC), constant voltage top-off (CV), and charge complete (done). If the battery voltage is below 2.55V, the charger is pre-charging with 90mA until prequalification upper threshold is reach or the maximum precharge time (30min for the MAX8939 or 12min for the MAX8939A and MAX8939B) reached. The precharge timer is reset when CHG\_IN is reasserted, and the charger starts charging if the battery voltage is below the precharge threshold. When the charger is in precharge mode, an LED indicator (LED3) and the SAFE\_OUT LDO are turned on; all other functions are disabled.

Once the battery voltage has passed the pregualification upper threshold, the charger enters the fast-charge stage. An analog soft-start is used when entering fast charge to reduce inrush current on the input supply. When fastcharge is in progress, a safety timer is enabled and STATUS can be read out of register 0x02 bit 4. For the MAX8939/ MAX8939A, the CHG\_EN is cleared and starts charging if CHG\_IN is asserted. The MAX8939B clears CHG\_EN only if RESET is logic-low. By pulling RESET logic-high, the charger is disabled or enabled depending on the state of the CHG\_EN bit. When CHG\_IN is asserted, an interrupt occurs, and the host can control the state of the CHG IN bit. The fast-charge current and safety timer are programmable through the I2C interface. The safety timers are reset if the charger is disabled and start a new cycle when the charger is enabled. The default battery regulation voltage (VSET) is 3.6V (MAX8939) or 3.5V (MAX8939A/MAX8939B), but can be programmed to 4.15V, 4.2V, or 4.25V for the MAX8939, or 3.85V, 4.05V, or 4.17V for the MAX8939A/MAX8939B.

When the battery voltage reaches VSET, the charger changes to top-off mode (CV). When entering top-off, an  $\overline{IRQ}$  is flagged to indicate that the charger is in constant voltage mode. Top-off mode keeps the voltage constant and the current falls slowly until the top-off current threshold is reached. An  $\overline{IRQ}$  is flagged to indicate charge is

# System Power Management for Mobile Handset

done. The top-off current threshold is a percentage of the fast-charge current, the threshold is programmable. When the top-off current threshold is set to 0% and restart is disabled, the top-off mode continues until the top-off timer expires. The top-off timer is programmable and can also be disabled. With the op-off threshold set to 0% and top-off timer disabled, the charger continuously charges the battery with a constant voltage and decreasing charge current. This makes it possible to control the charge algorithm through software, without influence of automatic maintaining charge.

To qualify charge as done, the current has to be below topoff current threshold or a timeout has occurred. To maintain the battery voltage, the charger can be programmed to restart once the battery voltage drops below a programmable threshold. When restart is enabled and the battery voltage drops below the restart threshold, the charger starts a new charging cycle by entering fast-charge.

If restart is disabled, the charger stops charging when done and does not maintain the battery voltage. When charge done occurs, an  $\overline{\text{IRQ}}$  is sent to the host and a flag is set in register 0x03. Reading the register disables the charger. The charger can be enabled by writing to register 0x09 bit 0 (CHG\_EN). If one of the safety timers (fast-charge or top-off) expires, an interrupt is sent to the host and a flag is set in register 0x03. The charger is disabled 5s after the safety times out.

If, at any point while charging the battery, the die temperature approaches the thermal regulation threshold (+100°C default), the ICs reduce the charging current so that the die temperature does not increase. This feature not only protects the ICs from overheating, but also allows the higher charge current without risking damage to the system.

Note all charger registers are reset to their default settings by power-on reset (POR) or RESET.

#### Charge On/Off Control

CHG is a logic hardware control input. Logic-high disables the charger and logic-low enables the charger.

- 1. CHG = logic-high, the charger is disabled when power pluck is asserted on CHG\_IN and register 0x09 has not been affected. When CHG changes logic state, a flag is set in the event register 0x03, and an interrupt occurs.
- 2. CHG = Logic-low, the charger is enabled and starts charging if charging conditions are within operating limits.

Once the CHG\_CONTROL\_A register 0x09 is accessed either by reading or writing, the CHG is ignored. When CHG changes status after register 0x09 has been accessed, only STATUS and EVENT\_A register is updated and an interrupt occurs. The CHG\_EN bit in CHG\_CONTROL\_A register 0x09 is always [1] by default. The CHG\_EN does not follow the status of CHG, and the charger is enabled just by reading the CHG\_CONTROL\_A register 0x09 and CHG is ignored. To avoid the charger enabling just by accessing the CHG\_CONTROL\_A register 0x09, write [0] in the CHG\_EN bit.

For the MAX8939 and MAX8939A, if the CHG\_IN is reconnected, the CHG is reset and the status of the charger is following the logic level on CHG, as long CHG\_CONTROL\_A register 0x09 is not affected. For the MAX8939B, the CHG is reset only by reasserting CHG\_IN if RESET or UVLO is low.

#### SAFE\_OUT

SAFE\_OUT is an LDO powered from the CHG\_IN input. SAFE\_OUT is enabled when a charger is detected (4.1V < VCHG\_IN < 10V (MAX8939) or 6.25V (MAX8939A/MAX8939B)) and provides a protected output regulated to 4.9V (5V max). Typically, SAFE\_OUT is used to power low-voltage USB systems and the precharge indicator.

#### Indicator LED

The LED3 output sinks 3mA (typ) to drive an indicator LED. LED3 is on by default and can be controlled by the host by I<sup>2</sup>C (bit 7 of the REG\_CONTROL register). Typically, this LED indicates charge status and SAFE\_OUT powers the LED as shown in Figure 1.

#### Charge Current Monitor (CHG\_MON)

CHG\_MON is an analog output used to monitor the charge current. CHG\_MON outputs a voltage proportional to the charge current with 1.2V corresponding to the programmed fast-charge current.

The CHG\_MON output includes ripple from loads on the battery. If this is not desired, connect a small  $0.01\mu F$  to  $0.1\mu F$  capacitor at the input of the ADC to filter the ripple.

#### Charger Watchdog Timer

During battery fast-charge, a watchdog monitoring function can be activated to ensure that the host processor has control of the charge algorithm. The watchdog timer is enabled through register REG\_CONTROL bit WD\_EN. When the charger is enabled by CHG\_EN or CHG\_IN, the watchdog timer starts counting. Within 5s of enabling the charger, the host must read or write register 0x09 or 0x0A to indicate it is alive. This resets the watchdog

# System Power Management for Mobile Handset

timer and the host must continue to read or write register 0x09 or 0x0A in intervals of under 5s. If the host takes more than 5s for reading or writing these registers, the watchdog timer expires, generates an interrupt, flags the watchdog timeout in register 0x03, and disables the charger (Figure 4).

#### Charge in Overvoltage Protection

To detect that a valid charger is asserted at CHG\_IN, an upper and lower threshold is defined. This threshold is different for the MAX8939, MAX8939A, and MAX8939B. See the *Electrical Characteristics* table for upper/lower threshold.

If an overvoltage condition occurs on CHG\_IN, a debounce timer is enabled and powers the charger down after a max delay of 324ms. When the charger is powered down, an interrupt occurs and a flag is set in event register A.

This OVP timer enables the possibility of using a low cost wall-plug adapter with poor voltage regulation. The charger continue charging and no interrupt occurs as long the OVP is not violating the max 324ms.

Fast thermal regulation ensures that the temperature does not exceed the programmed value (default is programmed at +100°C at high voltage < 30V and maximum charge current). If the junction temperature rises until the programmed value, the charge current is not switched off, but regulated down to a level to maintain the temperature around the programmed threshold.

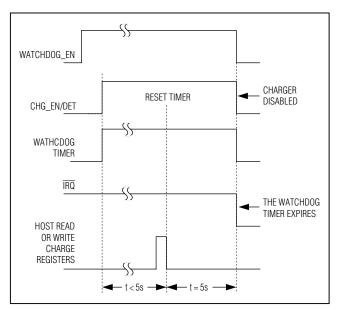


Figure 4. Watchdog Timing Diagram

### Interrupt Request (IRQ)

TRQ is an active-low, open-drain output signal (requires an external pullup resistor) that indicates that an interrupt event has occurred and that the event and status information are available in the event/status registers. Such information includes temperature and voltages inside the ICs fault conditions, etc. The event registers hold information about events that have occurred in the ICs. Events are triggered by a status change in the monitored signals. When an event bit is set in the event register, the IRQ signal is asserted (unless IRQ is masked by a bit in the IRQ mask register). The IRQ is also masked during power-up and is not released until the event registers have been read. Each event register is reset to its initial condition after being read. The IRQ is not released until all the event registers have been read. New events that occur during read-out of the event registers are held until all the event registers have been read to, ensuring that the host processor does not miss them.

PWR\_ON\_CMP is an open-drain output used to wake-up a sleeping baseband. PWR\_ON\_CMP is activated when a charger is detected (VCHG\_IN is between 4.1V and 10V (MAX8939) or 6.25V (MAX8939A/MAX8939B)) and the battery voltage is above the UVLO threshold. If the battery has already reached the UVLO upper threshold, the charger is detected by a rising edge. When such an

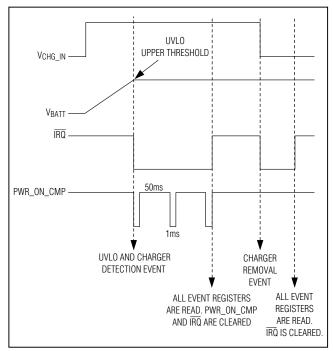


Figure 5. PWR\_ON\_CMP Sequence

# System Power Management for Mobile Handset

event is detected, the ICs start pulsing the PWR\_ON\_CMP output every 50ms, with a duty cycle of 98%. See Figure 5.

The event is also signaled by  $\overline{\text{IRQ}}$ , which is asserted when the UVLO upper threshold is reached and the CHG\_DET bit is set in register 0x04 (bit 6). The ICs continue pulsing PWR\_ON\_CMP until the EVENT registers 0x04 or 0x03 are read/written to or the charger safety timer expires. By reading/writing to the EVENT register, the register is cleared and PWR\_ON\_CMP and  $\overline{\text{IRQ}}$  returns to high impedance.

The events causing the PWR\_ON\_CMP activation are triggered by a rising edge signal that must remain valid for the duration of a 10ms debounce filter.

#### RESET IN

RESET\_IN is an active-low input signal to the ICs and is used to provide a full system reset inside the ICs. As long as RESET\_IN is logic-low, the ICs are not able to do anything (except the charger), until RESET\_IN is released. All registers are cleared except the STATUS and EVENT registers. When RESET\_IN is asserted, the EVENT\_B bit RESET is set. If the CHG\_IN voltage is valid and RESET\_IN is logic-low, the charger operates in its default state.

#### **Linear Regulators**

The ICs include four low-dropout linear regulators (LDOs). All LDOs are designed for low dropout, low noise, high PSRR, and low quiescent current to maximize battery life. When the battery voltage is above the UVLO upper threshold, the ICs' LDOs are ready to be turned on through the I<sup>2</sup>C interface. The guaranteed current drive capabilities for the LDOs are 400mA for LDO1, 200mA for LDO2 and LDO3, and 100mA for LDO4. The output voltage for each LDO is programmable through the I<sup>2</sup>C interface from 1.7V to 3.2V in 0.1V steps.

LDO1 can be enabled through a hardware pin LDO1\_EN. By connecting this pin to a logic-high level, the LDO enables automatically when the UVLO upper threshold is reached. The LDO can also be controlled by the LDO1\_EN bit of the REG\_CONTROL. When the

LDO1\_EN bit is written to, the LDO1 enable state reflects the value written, overriding the state of the LDO1\_EN pin. When the state of the LDO1\_EN pin changes, the LDO1 enable state is determined by the new state of the LDO1\_EN pin, overriding the LDO1\_EN bit value. This allows the system software to reduce quiescent power consumption by turning off LDO1 without impacting other logic that may utilize the same hardware control used for the LDO1\_EN pin.

#### **OUT1 Step-Up DC-DC Converter**

OUT1 is a fixed-frequency PWM step-up converter. The converter switches an internal power MOSFET and synchronous rectifier at a constant 2MHz frequency with varying duty cycle up to 75% to maintain constant output voltage as the input voltage and load current vary. Internal circuitry prevents any unwanted subharmonic switching in the critical step-down/step-up region by forcing a minimum 8% duty cycle.

OUT1 delivers up to 700mA to the load at a voltage programmable through I2C from 3.5V to 5V in 100mV steps.

#### Soft-Start OUT1

OUT1 soft-starts by charging CCOMP1 with a 100 $\mu$ A current source. During this time, the internal MOSFET is switching at the minimum duty cycle. Once VCOMP1 rises above 1V, the duty cycle increases until the output voltage reaches the desired regulation level. COMP1 is pulled to ground with a 30 $\Omega$  internal resistor during UVLO or shutdown.

#### **OUT2 White LED Driver**

OUT2 is the output from the step-up DC-DC converter for driving white LEDs. The converter is able to drive up to 60mA at up to 28V. The step-up converter is adaptive connected to the two low-dropout LED current regulators. The step-up converter operates at a fixed 2MHz switching frequency, enabling the use of very small external components to achieve a compact circuit area. For improved efficiency, the step-up converter automatically operates in pulse-skipping mode at light loads.

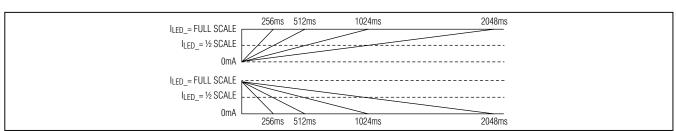


Figure 6. Ramp-Up/Ramp-Down

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#### Soft-Start OUT2

From shutdown, once LED1 or LED2 is enabled through the I<sup>2</sup>C interface, the step-up converter prepares for soft-start. CCOMP2 is quickly pulled to 1V by an internal pullup clamp. Since the LED\_ feedback node voltage is less than the regulation threshold (0.35V typ), 40µA current is sourced from the error amplifier and further charges CCOMP2. Once VCOMP2 reaches 1.25V, the step-up converter starts switching at a reduced duty cycle. As VCOMP2 rises, the step-up converter duty cycle increases.

When VLED1 or VLED2 reaches 0.35V (typ), the error amplifier stops sourcing current to CCOMP2, soft-start ends, and the control loop achieves regulation as VLED\_settles. The VCOMP2 where the step-up converter exits soft-start depends on the load. A 2.5V upper limit to VCOMP2 is imposed to aid in transient recovery and to allow maximum output for low input voltages. CCOMP2 is discharged to ground through a 20k $\Omega$  internal resistor whenever the step-up converter is turned off, allowing the device to reinitiate soft-start when it is enabled.

### LED1 and LED2 Current Regulators

Each current regulator drives a series string of LEDs. The maximum number of LEDs depends of maximum forward voltage of the LEDs at the maximum desired current. The total forward voltage of the LED string must be below 27.65V. The LED current is independently programmed using the I<sup>2</sup>C interface from 50µA to 25.25mA with a 128-step logarithmic dimming scheme.

#### Ramp-Up/-Down

The ICs' LED current regulators provide ramp- up and ramp-down functionality for smooth transitions between different brightness settings. A controlled ramp is used when the LED current level is changed, and when the LEDs are enabled or disabled. LED1 and LED2 have individual ramp control, making it possible to ramp

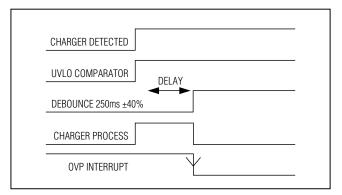


Figure 7. Timing of OVP Detection

different groups at different rates. The ramp-up and ramp-down times are controlled by the LED\_RU and LED\_RD control bits, and the ramps are enabled/disabled by the LED\_RAMP\_EN bits. The ICs increase or decrease the current one step every tramp/32 until the target LED current is reached.

#### Open/Short Detection

The ICs include comparators to detect open or shorted LEDs on LED1 and LED2. One comparator on each LED\_output detects when the voltage falls below 100mV, indicating an open LED fault. Another comparator on each LED\_output detects when the voltage rises above Vout2 - 1V, indicating a shorted LED fault. The fault-detection comparators are enabled only when the corresponding LED\_current regulator is enabled and provides a continuous monitor of the current regulator conditions.

Once a fault is detected, it is flagged in the EVENT\_B register and the  $\overline{IRQ}$  signal is asserted (unless masked in the IRQ\_MASK\_B register).

#### Overvoltage Protection

If the voltage on the OUT2 rises above 28V (typ), the LED driver is put into the shutdown state. This protects the ICs from excessive voltage in the event of an open-circuit LED.

#### Vibrator Driver

The vibrator driver is an LDO with PWM control (see Figure 8). The LDO output voltage is programmable through I<sup>2</sup>C to 1.3V, 2.5V, 3.0V, and V<sub>BATT</sub>.

The vibrator driver is driven with a PWM signal of duty cycle from 0% to 83% or 100%, with a repetition frequency of 23.8kHz divided into 84 steps. A PWM ratio set to greater than 83 results in the vibrator output being permanently enabled (100%). Figure 9 shows the output waveform at different output voltage and PWM settings. The duty cycle is set by the I<sup>2</sup>C interface, with a value greater than 0 enabling the PWM mode of operation. By using the enable/disable, an active stop is activated.

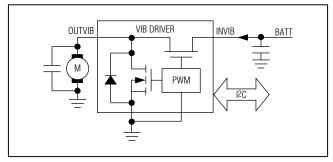


Figure 8. Vibrator Driver

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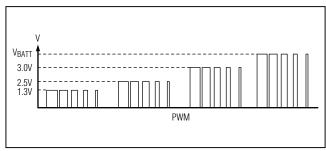


Figure 9. Vibrator Driver PWM Output

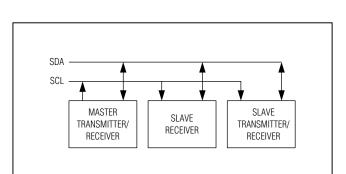


Figure 10. I<sup>2</sup>C Master/Slave Configuration

When the vibrator is disabled, an nFET switch turns on and shorts the vibrator to ground. At the same time the nFET switch works as a recovery diode to protect against reverse voltage from the vibrator.

The ICs include current protection that limits the current in case the vibrator motor locks up.

#### Thermal Shutdown

The ICs monitor the die temperature at the charger and each LDO and DC-DC regulator. When the temperature exceeds +160°C, the individual regulator is shutdown is shutdown. Once the die cools by 20°C, the regulator may be reenabled through the I<sup>2</sup>C interface.

The charger has independent thermal control circuitry that lowers the charge current to regulate the die temperature during the charge. The charger cannot exceed a temperature higher than the programmed level (default +100°C, +115°C max).

#### I<sup>2</sup>C Serial Interface

The serial bus consists of a bidirectional serial-data line (SDA) and a serial-clock input (SCL). See Figure 10. The ICs are slave-only devices, relying upon a master to generate the clock signal. The master initiates data transfer on the bus and generates SCL to permit data

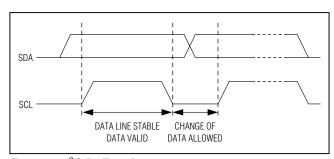


Figure 11. I<sup>2</sup>C Bit Transfer

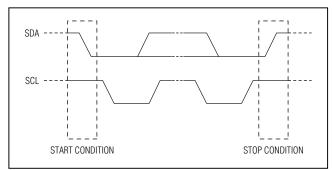


Figure 12. I<sup>2</sup>C START and STOP Conditions

transfer. The I<sup>2</sup>C slave address is 0x62 for write operations and 0x63 for read operations.

 $I^2C$  is an open-drain bus. SDA and SCL require pullup resistors (500 $\Omega$  or greater). Optional (24 $\Omega$ ) resistors in series with SDA and SCL protect the IC inputs from high-voltage spikes on the bus lines. Series resistors also minimize crosstalk and undershoot on bus signals.

#### Data Transfer

One data bit is transferred during each SCL clock cycle. The data on SDA must remain stable during the high period of the SCL clock pulse (see Figure 11). Changes in SDA while SCL is high are control signals (see the *START and STOP Conditions* section for more information).

Each transmit sequence is framed by a START (S) condition and a STOP (P) condition. Each data packet is 9 bits long; 8 bits of data followed by the acknowledge bit. The ICs support data transfer rates with SCL frequencies up to 400kHz.

#### START and STOP Conditions

When the serial interface is inactive, SDA and SCL idle high. A master device initiates communication by issuing a START condition. A START condition is a high-to-low tran-

# System Power Management for Mobile Handset

sition on SDA with SCL high. A STOP condition is a low-to-high transition on SDA, while SCL is high (Figure 12).

A START condition from the master signals the beginning of a transmission to the ICs. The master terminates transmission by issuing a not acknowledge followed by a STOP condition (see the *Acknowledge* section for more information). The STOP condition frees the bus. To issue a series of commands to the slave, the master may issue REPEATED START (Sr) commands instead of a STOP command to maintain control of the bus. In general, a REPEATED START command is functionally equivalent to a regular start command.

When a STOP condition or incorrect address is detected, the ICs internally disconnect SCL from the serial inter-

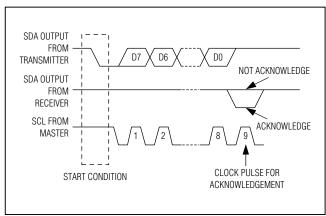


Figure 13. I<sup>2</sup>C Acknowledge

face until the next START condition, minimizing digital noise and feedthrough.

#### Acknowledge

Both the master and the ICs (slave) generate acknowledge bits when receiving data. The acknowledge bit is the last bit of each 9-bit data packet. To generate an acknowledge (A), the receiving device must pull SDA low before the rising edge of the acknowledge-related clock pulse (ninth pulse) and keep it low during the high period of the clock pulse (Figure 13). To generate a not acknowledge (NA), the receiving device allows SDA to be pulled high before the rising edge of the acknowledge-related clock pulse and leaves it high during the high period of the clock pulse.

Monitoring the acknowledge bits allows for detection of unsuccessful data transfers. An unsuccessful data transfer occurs if a receiving device is busy or if a system fault has occurred. In the event of an unsuccessful data transfer, the bus master should reattempt communication at a later time.

#### Slave Address

A bus master initiates communication with a slave device (ICs) by issuing a START condition followed by the slave address. The slave address byte consists of 7 address bits (0110001) and a read/write bit (R/W). After receiving the proper address, the ICs issue an acknowledge by pulling SDA low during the ninth clock cycle.

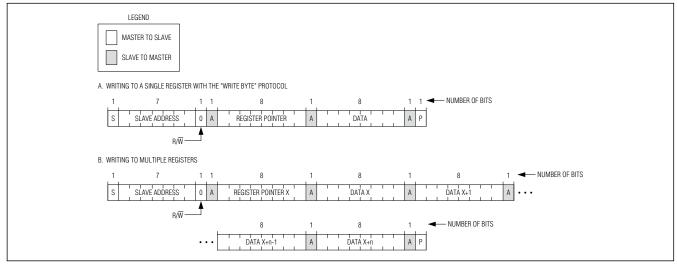


Figure 14. Writing to the MAX8939/MAX8939A/MAX8939B SMBus is a trademark of Intel Corp.

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#### Write Operations

The ICs recognize the write byte protocol as defined in the SMBus™ specification and shown in section A of Figure 14. The write byte protocol allows the I²C master device to send 1 byte of data to the slave device. The write byte protocol requires a register pointer address for the subsequent write. The ICs acknowledge any register pointer even though only a subset of those registers actually exists in the device. The write byte protocol is as follows:

- 1) The master sends a START command.
- 2) The master sends the 7-bit slave address followed by a write bit (0x62).
- 3) The addressed slave asserts an acknowledge by pulling SDA low.
- 4) The master sends an 8-bit register pointer.
- 5) The slave acknowledges the register pointer.
- 6) The master sends a data byte.
- 7) The slave updates with the new data.
- 8) The slave acknowledges the data byte.
- 9) The master sends a STOP condition.

In addition to the write-byte protocol, the ICs can write to multiple registers as shown in section B of Figure 14. This protocol allows the I<sup>2</sup>C master device to address the slave only once and then send data to a sequential block of registers starting at the specified register pointer.

Use the following procedure to write to a sequential block of registers:

1) The master sends a START command.

- 2) The master sends the 7-bit slave address followed by a write bit (0x62).
- The addressed slave asserts an acknowledge by pulling SDA low.
- 4) The master sends the 8-bit register pointer of the first register to write.
- 5) The slave acknowledges the register pointer.
- 6) The master sends a data byte.
- 7) The slave updates with the new data.
- 8) The slave acknowledges the data byte.
- 9) Steps 6 to 8 are repeated for as many registers in the block, with the register pointer automatically incremented each time.
- 10) The master sends a STOP condition.

#### Read Operations

The method for reading a single register (byte) is shown in section A of Figure 15. To read a single register:

- 1) The master sends a START command.
- 2) The master sends the 7-bit slave address followed by a write bit (0x62).
- 3) The addressed slave asserts an acknowledge by pulling SDA low.
- 4) The master sends an 8-bit register pointer.
- 5) The slave acknowledges the register pointer.
- 6) The master sends a repeated START condition.
- 7) The master sends the 7-bit slave address followed by a read bit (0x063).

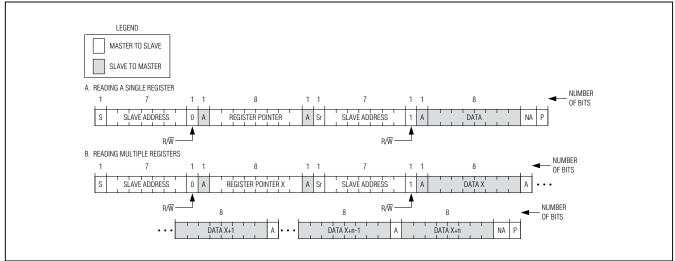


Figure 15. Reading from the MAX8939/MAX8939A/MAX8939B

# System Power Management for Mobile Handset

- 8) The slave asserts an acknowledge by pulling SDA low.
- 9) The slave sends the 8-bit data (contents of the register).
- 10) The master asserts a not acknowledge by keeping SDA high.
- 11) The master sends a STOP condition.

In addition, the ICs can read a block of multiple sequential registers as shown in section B of Figure 15. Use the following procedure to read a sequential block of registers:

- 1) The master sends a START command.
- 2) The master sends the 7-bit slave address followed by a write bit (0x62).
- The addressed slave asserts an acknowledge by pulling SDA low.

- 4) The master sends an 8-bit register pointer of the first register in the block.
- 5) The slave acknowledges the register pointer.
- 6) The master sends a REPEATED START condition.
- 7) The master sends the 7-bit slave address followed by a read bit (0x063).
- 8) The slave asserts an acknowledge by pulling SDA low.
- 9) The slave sends the 8-bit data (contents of the register).
- 10) The master asserts an acknowledge by pulling SDA low when there is more data to read, or a not acknowledge by keeping SDA high when all data has been read.
- 11) Steps 9 and 10 are repeated for as many registers in the block, with the register pointer automatically incremented each time.
- 12) The master sends a STOP condition.

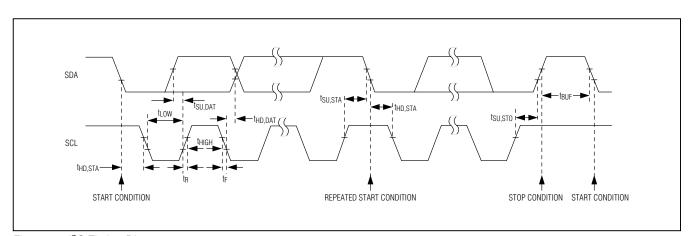


Figure 16. I<sup>2</sup>C Timing Diagram

### Table 2. Register Access Types

SYMBOL	REGISTER TYPE	NOTES
R	Read only	A field which is either static or is updated only by hardware. Value written by software is ignored by hardware; that is, software may write any value to this field without affecting hardware behavior.
W	Write only	_
R/W	Read/write	Hardware updates of this field are visible by software read and software updates of this field are visible by a hardware read.
RH	Read only; hardware affected	_
R&C	Read and clear	_
NASR	Not affected by software reset	_

# System Power Management for Mobile Handset

**Table 3. Operating Mode** 

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REGISTER	ACCESS TYPE	REGISTER POINTER	POWER-ON DEFAULT	MSB BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	LSB BIT 0
CHIP_ID1	R	0x00	0x56				Die type int	ormation			
CHIP_ID2	R	0x01	0x04 (MAX8939) 0x06 (MAX8939A) 0x09 (MAX8939B)	Die type and mask revision information							
STATUS	R	0x02	0x00	Reserved	CHG_DET	TOP_OFF	FAST_ CHG	LDO1_ HWEN	TEMP_ REG	DONE	CHG
EVENT_A	R&C	0x03	0x00	TEMP_ REG	CHG_OVP_ IN	RESTART	DONE	TOP_OFF	WDOG_ TIMEOUT	TIME_ OUT	CHG
EVENT_B	R&C	0x04	0x00	CHG_REM	CHG_DET	UVLO	RESET	OVERTEMP	LED2_ FAULT	LED1_ FAULT	LDO1_ HWEN
IRQ_MASK_A	W	0x03	0xFF	TEMP_ REG	CHG_ OVP_IN	RESTART	DONE	TOP_OFF	WDOG_ TIMEOUT	TIME_ OUT	CHG
IRQ_MASK_B	W	0x04	0xEF	CHG_REM	CHG_DET	UVLO	RESET	OVERTEMP	LED2_ FAULT	LED1_ FAULT	LDO1_ HWEN
REG_CONTROL	R/W	0x05	0x80	LED3_EN	WD_EN	BOOST2_ EN	BOOST1_ EN	LDO4_EN	LDO3_EN	LDO2_EN	LDO1_EN
LDO1/LDO2	R/W	0x06	0x1C		LDC	)2			LDC	)1	
LDO3/LDO4	R/W	0x07	0xBB		LDC	)4			LDC	)3	
BOOST1	R/W	0x08	0x0F		Reser	ved			B009	ST1	
CHG_CONTROL_A	R/W	0x09	0x1F	FAST_CHARGE RESTART TOP_OFF CHG_E		CHG_EN					
CHG_CONTROL_B	R/W	0x0A	0x20	TOPOF	F_TIME	TEMP	_REG	CC <sup>-</sup>	TR	VS	ET
LED_RAMP_1	R/W	0x0B	0x80	VIB_VOLTAGE LED1_RD LED1_RU							
LED_RAMP_2	R/W	0x0C	0x00	LED2_ LED1_ LED2_RD LED2_RU							
LED1	R/W	0x0D	0x00	EN ILED1							
LED2	R/W	0x0E	0x00	EN ILED2							
VIB	R/W	0x0F	0x00	EN		,		SPEED			

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### Table 4. CHIP ID1

REGISTER NAME	CHIP_ID1
Register Pointer	0x00
Reset Value	0x56
Туре	R

BIT	TYPE	NAME	DESCRIPTION	DEFAULT
0–7	R	Die type	BCD characters 69	0x56

### Table 5. CHIP\_ID2

REGISTER NAME	CHIP_ID2
Register Pointer	0x01
Reset Value	0x04 (MAX8939), 0x06 (MAX8939A), 0x09 (MAX8939B)
Туре	R

BIT	TYPE	NAME	DESCRIPTION	DEFAULT
0–7	R	Mask Revision	BCD characters 01	0x04 (MAX8939), 0x06 (MAX8939A) 0x09 (MAX8939B)

### **Table 6. STATUS**

REGISTER NAME	STATUS
Register Pointer	0x02
Reset Value	0x00
Туре	R

BIT	TYPE	NAME	DESCRIPTION	DEFAULT
0	R	CHG	Charger disabled	0
1	R	DONE	Fast-charging complete	0
2	R	TEMP_REG	Charger in thermal regulation	0
3	R	LDO1_HWEN	Enable pin status	0
4	R	FAST_CHG	Fast charging in progress (CC)	0
5	R	TOP_OFF	Top off in progress (CV)	0
6	R	CHG_DET	PWR_ON_CMP asserted by charger detection	0
7	R	Reserved	_	0

# System Power Management for Mobile Handset

#### Table 7. EVENT A

REGISTER NAME	EVENT_A
Register Pointer	0x03
Reset Value	0x00
Туре	R/R&C

BIT	TYPE	NAME	DESCRIPTION	DEFAULT
0	R&C	CHG	Charger disabled caused IRQ	0
1	R&C	TIME_OUT	FAST_CHG or TOP_OFF timeout caused IRQ	0
2	R&C	WDOG_TIMEOUT	Watchdog timeout caused IRQ	0
3	R&C	TOP_OFF	Entering TOP_OFF (CV) caused IRQ	0
4	R&C	DONE	Fast-charging complete caused IRQ	0
5	R&C	RESTART	Fast-charging restarted caused IRQ	0
6	R&C	CHG_OVP_IN	Charger input overvoltage caused IRQ	0
7	R&C	TEMP_REG	Charger in thermal regulation caused IRQ	0

### Table 8. EVENT\_B

REGISTER NAME	EVENT_B
Register Pointer	0x04
Reset Value	0x00
Туре	R/R&C

BIT	TYPE	NAME	DESCRIPTION	DEFAULT
0	R&C	LDO1_HWEN	Enable pin shift status caused IRQ	0
1	R&C	LED1_FAULT	Shorted or open circuitry caused IRQ	0
2	R&C	LED2_FAULT	Shorted or open circuitry caused IRQ	0
3	R&C	OVERTEMP	Overtemperature caused IRQ	0
4	R&C	RESET	RESET asserted	0
5	R&C	UVLO	Undervoltage lockout caused IRQ	0
6	R&C	CHG_DET	Charge detect = 1 if a valid charger is detected by a rising edge on CHG_IN	0
7	R&C	CHG_REM	Charger removal caused IRQ	0

**Note:** The EVENT registers hold information about events that have occurred in MAX8939/MAX8939A/MAX8939B. Events are triggered by a change in the status registers, which contains the status of the monitored signals. When an EVENT bit is set in the event register the  $\overline{IRQ}$  signal shall be asserted (unless the  $\overline{IRQ}$  is to be masked by a bit in the  $\overline{IRQ}$  mask register). The  $\overline{IRQ}$  is also masked during the power-up sequence and are not released until the event registers have been read for the first time. The event registers are automatically cleared during read-out operation automatically. The event registers may be read-out in page mode. New events that occur during read-out are delayed before they are passed to the event register, ensuring that the host controller does not miss them.

# System Power Management for Mobile Handset

### Table 9. IRQ\_MASK\_A

REGISTER NAME	IRQ_MASK_A
Register Pointer	0x03
Reset Value	0xFF
Type	W

BIT	TYPE	NAME	DESCRIPTION	DEFAULT
0	W	CHG	Charger disabled	1
1	W	TIME_OUT	FAST_CHG or TOP_OFF timeout caused IRQ	1
2	W	WDOG_TIMEOUT	Watchdog timeout caused IRQ	1
3	W	TOP_OFF	Entering TOP_OFF (CV) caused IRQ	1
4	W	DONE	Fast-charging complete caused IRQ	1
5	W	RESTART	Fast-charging restarted caused IRQ	1
6	W	CHG_OVP_IN	Charger input overvoltage caused IRQ	1
7	W	TEMP_REG	Charger in thermal regulation caused IRQ	1

### Table 10. IRQ\_MASK\_B

REGISTER NAME	IRQ_MASK_B
Register Pointer	0x04
Reset Value	0xEF
Type	W

BIT	TYPE	NAME	DESCRIPTION	DEFAULT
0	W	LDO1_HWEN	Enable pin shift status caused IRQ	1
1	W	LED1_FAULT	Shorted or open circuitry caused IRQ	1
2	W	LED2_FAULT	Shorted or open circuitry caused IRQ	1
3	W	OVERTEMP	Overtemperature caused IRQ	1
4	W	RESET	RESET asserted	0
5	W	UVLO	Undervoltage lockout caused IRQ	1
6	W	CHG_DET	PWR_ON_CMP asserted by charger detection and caused IRQ when UVLO upper	1
7	W	CHG_REM	Charger removal caused IRQ	1

# System Power Management for Mobile Handset

### Table 11. REG\_CONTROL

REGISTER NAME	REG_CONTROL
Register Pointer	0x05
Reset Value	0x80
Туре	R/W

BIT	TYPE	NAME	DESCRIPTION		DEFAULT
0	R/W	LDO1_EN	Disable LDO1 Enable LDO1	0 1	0
1	R/W	LDO2_EN	Disable LDO2 Enable LDO2	0 1	0
2	R/W	LDO3_EN	Disable LDO3 Enable LDO3	0 1	0
3	R/W	LDO4_EN	Disable LDO4 Enable LDO4	0 1	0
4	R/W	BOOST1_EN	Disable BOOST1 Enable BOOST1	0 1	0
5	R/W	BOOST2_EN	Disable BOOST2 (auto ON) Enable BOOST2	0 1	0
6	R/W	WD_EN	Disable watchdog charger Enable watchdog charger	0 1	0
7	R/W	LED3_EN	LED3 disabled LED3 enabled	0 1	1

### **Table 12. LDO1, LDO2**

REGISTER NAME	LDO1, LDO2
Register Pointer	0x06
Reset Value	0x1C
Туре	R/W

BIT	TYPE	NAME	DESCRIPTION		DEFAULT
0		R/W LDO1 0000 1.7V 0001 1.8 0010 1.9 0011 2.0 0100 2.1 0101 2.2	Set LDO1 output voltage.		
1	B/W		0001 1.8	1000 2.5 1001 2.6 1010 2.7	1100 (2.9V)
2	1,7,7,7		0100 2.1	1011 2.8 1100 2.9 1101 3.0	1100 (2.01)
3			0101 2.2 0110 2.3 0111 2.4	1110 3.1 1111 3.2	

# System Power Management for Mobile Handset

### Table 12. LDO1, LDO2 (continued)

BIT	TYPE	NAME	D	ESCRIPTION	DEFAULT
4			Sets LDO2 output voltage.		
5	R/W		0000 1.7V <b>0001 1.8</b>	1000 2.5 1001 2.6	
		R/W	LDO2	0010 1.9 0011 2.0	1010 2.7 1011 2.8
6			0100 2.1	1100 2.9	
_			0101 2.2	1101 3.0	
/			0111 2.4	1111 3.2	

### Table 13. LDO3, LDO4

REGISTER NAME	LDO3, LDO4
Register Pointer	0x07
Reset Value	0xBB
Туре	R/W

BIT	TYPE	NAME	DE	SCRIPTION	DEFAULT
0			Set LDO3 output voltage.		
1			0000 1.7V 0001 1.8	1000 2.5 1001 2.6	
	R/W	LDO3	0010 1.9 0011 2.0	1010 2.7 <b>1011 2.8</b>	1101 (2.8V)
2			0100 2.1 0101 2.2	1100 2.9 1101 3.0	
3			0110 2.3	1110 3.1	
			0111 2.4	1111 3.2	
4			Sets LDO4 output voltage.		
			0000 1.7V	1000 2.5	
5			0001 1.8	1001 2.6	
	R/W	LDO4	0010 1.9	1010 2.7	1011 (2.8V)
6			0011 2.0	1011 2.8	
			0100 2.1	1100 2.9	
			0101 2.2	1101 3.0	
7			0110 2.3 0111 2.4	1110 3.1 1111 3.2	

# System Power Management for Mobile Handset

### Table 14. BOOST1

REGISTER NAME	BOOST1
Register Pointer	0x08
Reset Value	0x0F
Туре	R/W

BIT	TYPE	NAME	DESC	RIPTION	DEFAULT
0			Set OUT1 voltage.		
1	R/W	BOOST1	0000 3.5V 0001 3.6 0010 3.7	1000 4.3V 1001 4.4 1010 4.5	1111 (5.0V)
2		ВООЗТТ	0011 3.8 0100 3.9 0101 4.0	1011 4.6 1100 4.7 1101 4.8	1111 (3.0V)
3			0110 4.1 0111 4.2	1110 4.9 1111 5.0	
4					
5		Reserved			_
6		rioscived			
7					

### Table 15. CHG\_CONTROL\_A

REGISTER NAME	CHG_CONTROL_A
Register Pointer	0x09
Reset Value	0x1F
Туре	R/W

BIT	TYPE	NAME	DESCRIPTION DEFA		DEFAULT	
0	R/W	CHG_EN	Disable charger Enable charger		0 1	1
1	DAM	TOD OFF	To a off a company the control of	10% 20%	00	11
2	R/W	TOP_OFF	Top-off current threshold	30% <b>0%</b>	10 11	11

# System Power Management for Mobile Handset

Table 15. CHG\_CONTROL\_A (continued)

BIT	TYPE	NAME		DESCRIPTION			DEFAULT						
3					200mV	00							
	R/W	RESTART	Restart threshold		300mV	01	11						
4	11/00	ILSTAIL	Trestait tillesiloid		400mV	10	"						
					Disable	11							
					90mA	000							
5			MAYO	MAX8939/	270mA	001							
				•	450mA	010							
											MAX8939A/ MAX8939B	630mA	011
6		Fast-charge	IVIAAO939D	765mA	100								
	R/W	FAST_CHARGE	current		850mA	101	000						
	Guiterit	Current	MANAGOO	1020mA	110								
7			MAX8939	1275mA	111								
/				MAX8939A/	120mA	110							
				MAX8939B	180mA	111							

**Note:** Accessing this register resets the watchdog timer. Fast-charge current values are maximum value. Real current may be lower by 10%.

### Table 16. CHG\_CONTROL\_B

REGISTER NAME	CHG_CONTROL_B
Register Pointer	0x0A
Reset Value	0x20
Type	R/W

BIT	TYPE	NAME		DESCRIPTION	DESCRIPTION					
0				MAX8939	<b>3.60V</b> 4.15V 4.20V 4.25V	00 01 10 11				
1	- R/W	VSET	Charge voltage	MAX8939A/ MAX8939B	<b>3.50V</b> 3.85V 4.05V 4.17V	00 01 10 11	00			
2	R/W	CCTR	Fast-charge timer for	MAX8939/ MAX8939A/ MAX8939B	60min 24min	00 00	00			
3	n/vv	maximum	maximum operation time M/M/				MAX8939/ MAX8939A/ MAX8939B	120min 240min Disabled	01 10 11	00
4	DAM	TEMP_REG	The recel requilation		+70°C +85°C	00 01	10			
5	R/W	TEIVII _TIEG THEITHAI TEGUIALIO	Thermal regulation	I	<b>+100°C</b> +115°C	10 11	10			
6	DAM	TOPOSE TIME	Top-off timer for co	onstrained	<b>30min</b> 60min	00 01	00			
7	- R/W	TOPOFF_TIME	operation		120min Disabled	10 11	00			

**Note:** Accessing this register resets the watchdog timer.

# System Power Management for Mobile Handset

### Table 17. LED\_RAMP\_1

REGISTER NAME	LED_RAMP_1
Register Pointer	0x0B
Reset Value	0x80
Туре	R/W

BIT	TYPE	NAME	DESCRIPTION			DEFAULT
0				0s 0.128s 0.256s	000 001 010	
1	R/W	LED1_RU	Full-scale ramp time	0.512s 0.760s	011 100	000
2				1.000s 2.000s 4.000s	101 110 111	
3				0s 0.128s 0.256s	000 001 010	
4	R/W	LED1_RD	Full-scale ramp time	0.512s 0.760s 1.000s	011 100 101	000
5				2.000s 4.000s	110 111	
6	R/W	VIB_VOLTAGE	Maximum output voltage from VIB	1.3V 2.5V	00 01	10
7	11/77	VID_VOLIAGE	driver	<b>3.0V</b> Bypass	10 11	10

# System Power Management for Mobile Handset

### Table 18. LED\_RAMP\_2

REGISTER NAME	LED_RAMP_2
Register Pointer	0x0C
Reset Value	0x00
Туре	R/W

BIT	TYPE	NAME	DESCRIPTION			DEFAULT
0				0s 0.128s	000 001	
1	R/W	LED2_RU	Full-scale ramp time	0.256s 0.512s 0.760s	010 011 100	000
2				1.000s 2.000s 4.000s	101 110 111	
3				0s 0.128s	000 001	
4	R/W	LED2_RD	Full-scale ramp time	0.256s 0.512s 0.760s	010 011 100	000
5				1.000s 2.000s 4.000s	101 110 111	
6	R/W	LED1_RAMP_EN	<b>Disable LED1 RAMP</b> Enable LED1 RAMP		0	0
7	R/W	LED2_RAMP_EN	<b>Disable LED2 RAMP</b> Enable LED2 RAMP		0 1	0

### Table 19. LED1

REGISTER NAME	LED1
Register Pointer	0x0D
Reset Value	0x00
Туре	R/W

# System Power Management for Mobile Handset

Table 19. LED1 (continued)

BIT	TYPE	NAME		DESCRIPTION					DEFAULT
			0x00	0.05mA	0x2B	6.15mA	0x56	15.15mA	
			0x01	0.10	0x2C	6.35	0x57	15.35	
0			0x02	0.20	0x2D	6.50	0x58	15.60	
U			0x03	0.25	0x2E	6.70	0x59	15.80	
			0x04	0.35	0x2F	6.90	0x5A	16.05	
			0x05	0.45	0x30	7.10	0x5B	16.30	
	1		0x06	0.55	0x31	7.30	0x5C	16.50	
			0x07	0.65	0x32	7.45	0x5D	16.75	
4			0x08	0.75	0x33	7.65	0x5E	17.00	
1			0x09	0.85	0x34	7.85	0x5F	17.25	
			0x0A	1.00	0x35	8.05	0x60	17.45	
			0x0B	1.10	0x36	8.25	0x61	17.70	
	1		0x0C	1.20	0x37	8.45	0x62	17.95	
			0x0D	1.35	0x38	8.65	0x63	18.20	
			0x0E	1.45	0x39	8.85	0x64	18.45	
2			0x0F	1.60	0x3A	9.05	0x65	18.65	
			0x10	1.75	0x3B	9.25	0x66	18.90	
			0x11	1.85	0x3C	9.45	0x67	19.15	
	-		0x12	2.00	0x3D	9.65	0x68	19.40	
			0x13	2.15	0x3E	9.90	0x69	19.65	
			0x14	2.30	0x3F	10.1	0x6A	19.90	
3	R/W	ILED1	0x15	2.45	0x40	10.3	0x6B	20.15	0000000
			0x16	2.60	0x41	10.5	0x6C	20.40	
			0x17	2.75	0x42	10.7	0x6D	20.65	
	-		0x18	2.9	0x43	10.9	0x6E	20.90	
			0x19	3.05	0x44	11.15	0x6F	21.15	
			0x1A	3.2	0x45	11.35	0x70	21.40	
4			0x1B	3.35	0x46	11.55	0x71	21.65	
			0x1C	3.5	0x47	11.8	0x72	21.90	
			0x1D	3.65	0x48	12.00	0x73	22.15	
	-		0x1E	3.85	0x49	12.20	0x74	22.40	
			0x1F	4	0x4A	12.45	0x75 0x76	22.65 22.90	
			0x20	4.15	0x4B	12.65	0x76	23.15	
5			0x21	4.35	0x4C	12.85	0x77 0x78	23.40	
			0x22	4.55	0x4D	13.10	0x76	23.70	
			0x23	4.7	0x4E	13.30	0x79 0x7A	23.70	
	1		0x24	4.9	0x4F	13.55	0x7A 0x7B	24.20	
			0x25	5.05	0x50	13.75	0x7B 0x7C	24.20	
			0x26	5.25	0x51	14.00	0x7D	24.70	
6			0x27	5.45	0x52	14.20	0x7E	25.00	
5			0x28	5.6	0x53	14.45	0x7E 0x7F	25.00	
			0x29 0x2A	5.8 5.95	0x54 0x55	14.65 14.90	OA71	20.20	
			UNZA						
7	R/W	EN			i <b>sable LEI</b>			0	0
	Enable LED1							1	

# System Power Management for Mobile Handset

### Table 20. LED2

REGISTER NAME	LED2
Register Pointer	0x0E
Reset Value	0x00
Туре	R/W

BIT	TYPE	NAME		DESCRIPTION						
			0x00	0.05mA	0x2B	6.15mA	0x56	15.15mA		
			0x01	0.10	0x2C	6.35	0x57	15.35		
0			0x02	0.20	0x2D	6.50	0x58	15.60		
			0x03	0.25	0x2E	6.70	0x59	15.80		
			0x04	0.35	0x2F	6.90	0x5A	16.05		
			0x05	0.45	0x30	7.10	0x5B	16.30		
			0x06	0.55	0x31	7.30	0x5C	16.50		
			0x07	0.65	0x32	7.45	0x5D	16.75		
1			0x08	0.75	0x33	7.65	0x5E	17.00		
'			0x09	0.85	0x34	7.85	0x5F	17.25		
			0x0A	1.00	0x35	8.05	0x60	17.45		
			0x0B	1.10	0x36	8.25	0x61	17.70		
			0x0C	1.20	0x37	8.45	0x62	17.95		
			0x0D	1.35	0x38	8.65	0x63	18.20		
			0x0E	1.45	0x39	8.85	0x64	18.45		
2			0x0F	1.60	0x3A	9.05	0x65	18.65		
			0x10	1.75	0x3B	9.25	0x66	18.90		
			0x11	1.85	0x3C	9.45	0x67	19.15		
	1		0x12	2.00	0x3D	9.65	0x68	19.40		
			0x13	2.15	0x3E	9.90	0x69	19.65		
			0x14	2.30	0x3F	10.10	0x6A	19.90		
3	R/W	ILED2	0x15	2.45	0x40	10.30	0x6B	20.15	0000000	
			0x16	2.60	0x41	10.50	0x6C	20.40		
			0x17	2.75	0x42	10.70	0x6D	20.65		
	-		0x18	2.90	0x43	10.90	0x6E	20.90		
			0x19	3.05	0x44	11.15	0x6F	21.15		
			0x1A	3.20	0x45	11.35	0x70	21.40		
4			0x1B	3.35	0x46	11.55	0x71	21.65		
			0x1C	3.50	0x47	11.80	0x72	21.90		
			0x1D	3.65	0x48	12.00	0x73	22.15		
	-		0x1E	3.85	0x49	12.20	0x74	22.40		
			0x1F	4.00	0x4A	12.45	0x75	22.65		
					0x20	4.15	0x4B	12.65	0x76	22.90
5			0x21	4.35	0x4C	12.85	0x77	23.15		
			0x22	4.55	0x4D	13.10	0x78	23.40		
			0x23	4.70	0x4E	13.30	0x79	23.70		
	-		0x24	4.90	0x4F	13.55	0x7A	23.95		
			0x25	5.05	0x50	13.75	0x7B	24.20		
			0x26	5.25	0x51	14.00	0x7C	24.45		
6			0x27	5.45	0x52	14.20	0x7D	24.70		
			0x28	5.60	0x53	14.45	0x7E	25.00		
			0x29	5.80	0x54	14.65	0x7F	25.25		
			0x2A	5.95	0x55	14.90				
7	DAM	ENI		D	sable LEI	02		0	0	
	R/W	EN		E	nable LEC	)2		1	0	

# System Power Management for Mobile Handset

Table 21. VIB

REGISTER NAME	VIB
Register Pointer	0x0F
Reset Value	0x00
Туре	R/W

BIT	TYPE	NAME	DESCRIPTION						DEFAULT		
			0x00	0.00%	0x21	39.2%	0x42	78.5%			
			0x01	1.19	0x22	40.4	0x43	79.7			
0			0x02	2.38	0x23	41.6	0x44	80.9			
			0x03	3.57	0x24	42.8	0x45	82.1			
	-		0x04	4.76	0x25	44	0x46	100			
			0x05	5.95	0x26	45.2		100			
4			0x06	7.14	0x27	46.4	0xFF				
1			0x07	8.33	0x28	47.6					
			0x08	9.52	0x29	48.8					
	1		0x09	10.7	0x2A	50.0					
			0x0A	11.9	0x2B	51.1					
2			0x0B	13.0	0x2C	52.3					
			0x0C	14.2	0x2D	53.5					
			0x0D	15.4	0x2E	54.7					
			0x0E	16.6	0x2F	55.9					
		R/W SPEED	0x0F	17.8	0x30	57.1					
3	D///		0x10	19.0	0x31	58.3			0000000		
	'',**	0, 225	0x11	20.2	0x32	59.5			0000000		
	_		0x12	21.4	0x33	60.7					
			0x13	22.6	0x34	61.9					
			0x14	23.8	0x35	63.0					
4			0x15	25.0	0x36	64.2					
			0x16	26.1	0x37	65.4					
					0x17	27.3	0x38	66.6			
	-		0x18	28.5	0x39	67.8					
			0x19	29.7	0x3A	69.0					
			0x1A	30.9	0x3B	70.2					
5			0x1B	32.1	0x3C	71.4					
			0x1C	33.3	0x3D	72.6					
			0x1D	34.5	0x3E	73.8					
	1		35.7	0x3F	75.0						
			0x1F	36.9	0x40	76.1					
6			0x20	38.0	0x41	77.3					
7	R/W	EN	Disable VIB					0	0		
	1 1/ V V	LIN	Enable VIB					1	U		

# System Power Management for Mobile Handset

### Applications Information

#### **Inductor Selection**

The OUT1 step-up converter is designed to use a 2.2µH to 10µH inductor (see Table 22). To prevent core saturation, ensure that the inductor saturation current rating exceeds the peak inductor current for the application. Calculate the worst-case peak inductor current with the following formula:

$$I_{PEAK} = \frac{V_{OUT} \times I_{OUT(MAX)}}{0.9 \times V_{IN(MIN)}} + \frac{V_{IN(MIN)} \times 0.5 \mu s}{2 \times L}$$

The OUT2 LED driver is optimized for using a 10µH inductor, although larger or smaller inductors may be used. Using a smaller inductance results in discontinuous current mode operation over a larger range of output power, whereas use of a larger inductance results in continuous conduction for most of the operating range.

To prevent core saturation, ensure that the inductor's saturation current rating exceeds the peak inductor current for the application. For larger inductor values and continuous conduction operation, calculate the worst-case peak inductor current with the following formula:

$$I_{PEAK} = \frac{V_{OUT} \times I_{OUT(MAX)}}{0.9 \times V_{IN(MIN)}} + \frac{V_{IN(MIN)} \times 0.5 \mu s}{2 \times L}$$

For small values of L in discontinuous conduction operation, IPEAK is 860mA (typ). Table 23 provides a list of recommended inductors.

#### **Capacitor Selection**

Ceramic capacitors are recommended due to their low ESR. Ensure that the capacitor maintains its capacitance over temperature and DC bias. Generally ceramic capacitors with X5R or X7R temperature characteristics perform well. Note that some small size ceramic capacitors fail to maintain their capacitance when a DC bias is applied and should be avoided. Place the capacitors as close as possible to the IC.

The recommended input and output capacitor values are shown in Figure 1, however, larger value capacitors can be used to further reduce ripple at the expense of size and higher cost.

#### **Compensation**

The OUT1 step-up converter is compensated for stability through an external compensation network from COMP1 to ground. A 2200pF ceramic capacitor is recommended.

The OUT2 LED driver is compensated for stability through an external compensation network from COMP2 to ground. A 0.22µF ceramic capacitor is recommended for most applications. Higher CCOMP2 values increase soft-start duration, as well as the time delay between enabling the step-up converter to initiating soft-start. See the *Soft-Start OUT2* section for more information.

Table 22. Recommended Inductors for L1

MANUFACTURER	PART	INDUCTANCE (µH)	DCR (mΩ)	ISAT (A)	DIMENSIONS (LTYP x WTYP x H <sub>MAX</sub> ) (mm)
Cooper (Coiltronics)	SD3114	2.2	110	1.74	3.0 x 3.0 x 1.45
FDK	MIPF2520	2.2	80	1.3	2.5 x 2.0 x 1.0
	MIPW3226	2.2	100	1.1	3.2 x 2.6 x 1.0
TDK	VLS3012ET VLS3010T	2.2 10	80 390	1.35 0.65	3 x 3 x 1.2 3 x 3 x 1.0
TOKO	DE2812C	2.7	75	1.8	3.0 x 3.2 x 1.2
TOKO	DE2812C	10	325	0.78	3.0 x 3.2 x 1.2

Table 23. Recommended Inductors for L2

MANUFACTURER	PART	INDUCTANCE (µH)	DCR (mΩ)	ISAT (A)	DIMENSIONS (LTYP x WTYP x HMAX) (mm)
TOKO	1098AS-100M	10	290	0.75	2.8 x 3.0 x 1.2
IONO	1069AS-220M	22	570	0.47	3 x 3 x 1.8
FDK	MIP3226D100M	10	160	0.9	3.2 x 2.6 x 1.0

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#### **Diode Selection**

The OUT2 LED converter uses an external rectifier diode. A Schottky diode is recommended due to its fast recovery time and low forward voltage drop. Ensure that the diode's average and peak current rating exceeds the average output current and peak inductor current. In addition, the diode's reverse breakdown voltage must exceed the maximum VOUT2.

#### **PCB Layout**

Due to fast switching waveforms and high current paths, careful PCB layout is required. Minimize trace lengths between the IC and the inductor, the diode, the input capacitor, and the output capacitor. Minimize trace lengths between the input and output capacitors and the

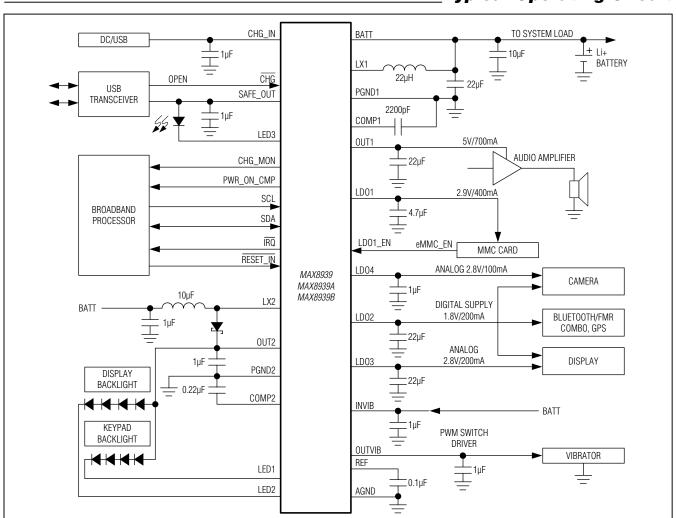
ICs' ground terminal, and place input and output capacitor grounds as close together as possible. Use separate power ground and analog ground copper areas, and connect them together at the output capacitor ground. Keep traces short, direct, and wide.

Keep noisy traces, such as the LX\_ node trace, away from sensitive analog circuitry. For improved thermal performance, maximize the copper area of the LX\_ and PGND\_ traces. Refer to the MAX8939/MAX8939A/MAX8939B Evaluation Kit for an example layout.

### **Chip Information**

PROCESS: BICMOS

### **Typical Operating Circuit**

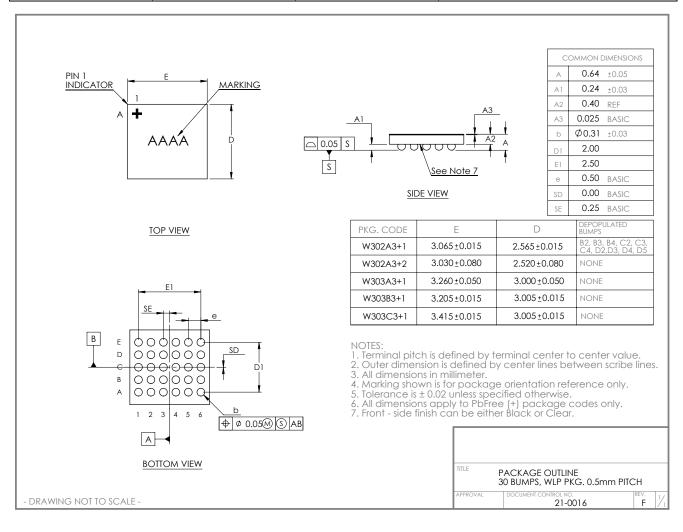


# System Power Management for Mobile Handset

### Package Information

For the latest package outline information and land patterns (footprints), go to <a href="https://www.maximintegrated.com/packages">www.maximintegrated.com/packages</a>. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
30 WLP	W302A3+2	<u>21-0016</u>	Refer to Application Note 1891



# System Power Management for Mobile Handset

### **Revision History**

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	5/11	Initial release	_
1	11/11	Added MAX8939A to data sheet	1–43
2	1/12	Revised LDO output accuracy, added <i>Charge On/Off Control</i> section, updated Figure 3	5–8, 19, 20, 21
3	2/12	Added new Note 3 to Electrical Characteristics table	2–8
4	11/12	Added MAX8939B to data sheet, corrected VSET voltage, updated TOCs21 and 22, updated Figure 3, updated Tables 10, 15, and 16	1–45
5	12/12	Updated LX1, LED1, and OUT2 specs	6, 8



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